



## K60 Sub-Family Data Sheet

Supports the following:

MK60N256VLQ100,  
MK60X256VLQ100,  
MK60N512VLQ100,  
MK60N256VMD100,  
MK60X256VMD100,  
MK60N512VMD100

### Features

- Operating Characteristics
  - Voltage range: 1.71 to 3.6 V
  - Flash write voltage range: 1.71 to 3.6 V
  - Temperature range (ambient): -40 to 105°C
- Performance
  - Up to 100 MHz ARM Cortex-M4 core with DSP instructions delivering 1.25 Dhrystone MIPS per MHz
- Memories and memory interfaces
  - Up to 512 KB program flash memory on non-FlexMemory devices
  - Up to 256 KB program flash memory on FlexMemory devices
  - Up to 256 KB FlexNVM on FlexMemory devices
  - 4 KB FlexRAM on FlexMemory devices
  - Up to 128 KB RAM
  - Serial programming interface (EzPort)
  - FlexBus external bus interface
- Clocks
  - 3 to 32 MHz crystal oscillator
  - 32 kHz crystal oscillator
  - Multi-purpose clock generator
- System peripherals
  - 10 low-power modes to provide power optimization based on application requirements
  - Memory protection unit with multi-master protection
  - 16-channel DMA controller, supporting up to 64 request sources
  - External watchdog monitor
  - Software watchdog
  - Low-leakage wakeup unit
- Security and integrity modules
  - Hardware CRC module to support fast cyclic redundancy checks
  - Hardware random-number generator
  - Hardware encryption supporting DES, 3DES, AES, MD5, SHA-1, and SHA-256 algorithms
  - 128-bit unique identification (ID) number per chip
- Human-machine interface
  - Low-power hardware touch sensor interface (TSI)
  - General-purpose input/output
- Analog modules
  - Two 16-bit SAR ADCs
  - Programmable gain amplifier (up to x64) integrated into each ADC
  - Two 12-bit DACs
  - Three analog comparators (CMP) containing a 6-bit DAC and programmable reference input
  - Voltage reference
- Timers
  - Programmable delay block
  - Eight-channel motor control/general purpose/PWM timer
  - Two 2-channel quadrature decoder/general purpose timers
  - IEEE 1588 timers
  - Periodic interrupt timers
  - 16-bit low-power timer
  - Carrier modulator transmitter
  - Real-time clock

## K60P144M100SF2



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Preliminary



- Communication interfaces
  - Ethernet controller with MII and RMII interface to external PHY and hardware IEEE 1588 capability
  - USB full-/low-speed On-the-Go controller with on-chip transceiver
  - Two Controller Area Network (CAN) modules
  - Three SPI modules
  - Two I2C modules
  - Five UART modules
  - Secure Digital host controller (SDHC)
  - I2S module

# Table of Contents

1	Ordering parts.....	5	6	Peripheral operating requirements and behaviors.....	21
1.1	Determining valid orderable parts.....	5	6.1	Core modules.....	22
2	Part identification.....	5	6.1.1	Debug trace timing specifications.....	22
2.1	Description.....	5	6.1.2	JTAG electricals.....	23
2.2	Format.....	5	6.2	System modules.....	26
2.3	Fields.....	5	6.3	Clock modules.....	26
2.4	Example.....	6	6.3.1	MCG specifications.....	26
3	Terminology and guidelines.....	6	6.3.2	Oscillator electrical specifications.....	28
3.1	Definition: Operating requirement.....	6	6.3.3	32kHz Oscillator Electrical Characteristics.....	30
3.2	Definition: Operating behavior.....	7	6.4	Memories and memory interfaces.....	31
3.3	Definition: Attribute.....	7	6.4.1	Flash (FTFL) electrical specifications.....	31
3.4	Definition: Rating.....	8	6.4.2	EzPort Switching Specifications.....	35
3.5	Result of exceeding a rating.....	8	6.4.3	Flexbus Switching Specifications.....	36
3.6	Relationship between ratings and operating requirements.....	8	6.5	Security and integrity modules.....	39
3.7	Guidelines for ratings and operating requirements.....	9	6.6	Analog.....	39
3.8	Definition: Typical value.....	9	6.6.1	ADC electrical specifications.....	39
3.9	Typical value conditions.....	10	6.6.2	CMP and 6-bit DAC electrical specifications.....	47
4	Ratings.....	10	6.6.3	12-bit DAC electrical characteristics.....	50
4.1	Thermal handling ratings.....	11	6.6.4	Voltage reference electrical specifications.....	53
4.2	Moisture handling ratings.....	11	6.7	Timers.....	54
4.3	ESD handling ratings.....	11	6.8	Communication interfaces.....	54
4.4	Voltage and current operating ratings.....	11	6.8.1	Ethernet switching specifications.....	55
5	General.....	12	6.8.2	USB electrical specifications.....	56
5.1	Nonswitching electrical specifications.....	12	6.8.3	USB DCD electrical specifications.....	56
5.1.1	Voltage and current operating requirements.....	12	6.8.4	USB VREG electrical specifications.....	57
5.1.2	LVD and POR operating requirements.....	13	6.8.5	CAN switching specifications.....	57
5.1.3	Voltage and current operating behaviors.....	14	6.8.6	DSPI switching specifications (low-speed mode).....	58
5.1.4	Power mode transition operating behaviors.....	14	6.8.7	DSPI switching specifications (high-speed mode).....	59
5.1.5	Power consumption operating behaviors.....	15	6.8.8	I2C switching specifications.....	61
5.1.6	EMC radiated emissions operating behaviors.....	18	6.8.9	UART switching specifications.....	61
5.1.7	Designing with radiated emissions in mind.....	19	6.8.10	SDHC specifications.....	61
5.1.8	Capacitance attributes.....	19	6.8.11	I2S switching specifications.....	62
5.2	Switching specifications.....	19	6.9	Human-machine interfaces (HMI).....	64
5.2.1	Device clock specifications.....	19	6.9.1	TSI electrical specifications.....	64
5.2.2	General switching specifications.....	20	7	Dimensions.....	65
5.3	Thermal specifications.....	21	7.1	Obtaining package dimensions.....	65
5.3.1	Thermal operating requirements.....	21	8	Pinout.....	65
5.3.2	Thermal attributes.....	21			

8.1 K60 Signal Multiplexing and Pin Assignments.....65      9 Revision History.....74  
8.2 K60 Pinouts.....72

# 1 Ordering parts

## 1.1 Determining valid orderable parts

Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to <http://www.freescale.com> and perform a part number search for the following device numbers: PK60 and MK60.

# 2 Part identification

## 2.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

## 2.2 Format

Part numbers for this device have the following format:

Q K## M FFF T PP CCC N

## 2.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

Field	Description	Values
Q	Qualification status	<ul style="list-style-type: none"> <li>M = Fully qualified, general market flow</li> <li>P = Prequalification</li> </ul>
K##	Kinetis family	<ul style="list-style-type: none"> <li>K60</li> </ul>
M	Flash memory type	<ul style="list-style-type: none"> <li>N = Program flash only</li> <li>X = Program flash and FlexMemory</li> </ul>

*Table continues on the next page...*

## Terminology and guidelines

Field	Description	Values
FFF	Program flash memory size	<ul style="list-style-type: none"><li>• 32 = 32 KB</li><li>• 64 = 64 KB</li><li>• 128 = 128 KB</li><li>• 256 = 256 KB</li><li>• 512 = 512 KB</li><li>• 1M0 = 1 MB</li></ul>
T	Temperature range (°C)	<ul style="list-style-type: none"><li>• V = -40 to 105</li><li>• C = -40 to 85</li></ul>
PP	Package identifier	<ul style="list-style-type: none"><li>• FM = 32 QFN (5 mm x 5 mm)</li><li>• FT = 48 QFN (7 mm x 7 mm)</li><li>• LF = 48 LQFP (7 mm x 7 mm)</li><li>• EX = 64 QFN (9 mm x 9 mm)</li><li>• LH = 64 LQFP (10 mm x 10 mm)</li><li>• LK = 80 LQFP (12 mm x 12 mm)</li><li>• MB = 81 MAPBGA (8 mm x 8 mm)</li><li>• LL = 100 LQFP (14 mm x 14 mm)</li><li>• MC = 121 MAPBGA (8 mm x 8 mm)</li><li>• LQ = 144 LQFP (20 mm x 20 mm)</li><li>• MD = 144 MAPBGA (13 mm x 13 mm)</li><li>• MF = 196 MAPBGA (15 mm x 15 mm)</li><li>• MJ = 256 MAPBGA (17 mm x 17 mm)</li></ul>
CCC	Maximum CPU frequency (MHz)	<ul style="list-style-type: none"><li>• 50 = 50 MHz</li><li>• 72 = 72 MHz</li><li>• 100 = 100 MHz</li><li>• 120 = 120 MHz</li><li>• 150 = 150 MHz</li></ul>
N	Packaging type	<ul style="list-style-type: none"><li>• R = Tape and reel</li><li>• (Blank) = Trays</li></ul>

## 2.4 Example

This is an example part number:

MK60N512VMD100

## 3 Terminology and guidelines

### 3.1 Definition: Operating requirement

An *operating requirement* is a specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip.

### 3.1.1 Example

This is an example of an operating requirement, which you must meet for the accompanying operating behaviors to be guaranteed:

Symbol	Description	Min.	Max.	Unit
V <sub>DD</sub>	1.0 V core supply voltage	0.9	1.1	V

## 3.2 Definition: Operating behavior

An *operating behavior* is a specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions.

### 3.2.1 Example

This is an example of an operating behavior, which is guaranteed if you meet the accompanying operating requirements:

Symbol	Description	Min.	Max.	Unit
I <sub>WP</sub>	Digital I/O weak pullup/pulldown current	10	130	μA

## 3.3 Definition: Attribute

An *attribute* is a specified value or range of values for a technical characteristic that are guaranteed, regardless of whether you meet the operating requirements.

### 3.3.1 Example

This is an example of an attribute:

Symbol	Description	Min.	Max.	Unit
CIN_D	Input capacitance: digital pins	—	7	pF

### 3.4 Definition: Rating

A *rating* is a minimum or maximum value of a technical characteristic that, if exceeded, may cause permanent chip failure:

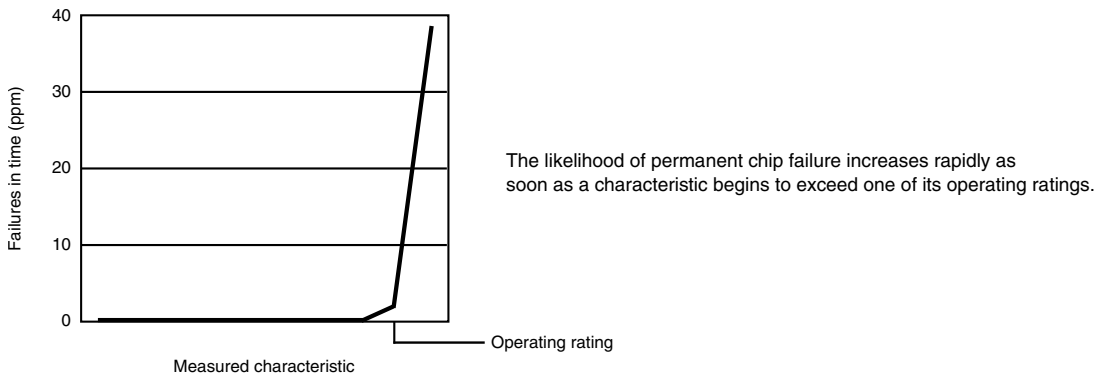
- *Operating ratings* apply during operation of the chip.
- *Handling ratings* apply when the chip is not powered.

#### 3.4.1 Example

This is an example of an operating rating:

Symbol	Description	Min.	Max.	Unit
V <sub>DD</sub>	1.0 V core supply voltage	-0.3	1.2	V

### 3.5 Result of exceeding a rating





### 3.6 Relationship between ratings and operating requirements

Operating or handling rating (min.)		Operating requirement (min.)		Operating requirement (max.)		Operating or handling rating (max.)	
<b>Fatal range</b> - Probable permanent failure	<b>Limited operating range</b> - No permanent failure - Possible decreased life - Possible incorrect operation	<b>Normal operating range</b> - No permanent failure - Correct operation	<b>Limited operating range</b> - No permanent failure - Possible decreased life - Possible incorrect operation	<b>Fatal range</b> - Probable permanent failure			
<b>Handling range</b> - No permanent failure							
-∞						∞	

### 3.7 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.

### 3.8 Definition: Typical value

A *typical value* is a specified value for a technical characteristic that:

- Lies within the range of values specified by the operating behavior
- Given the typical manufacturing process, is representative of that characteristic during operation when you meet the typical-value conditions or other specified conditions

Typical values are provided as design guidelines and are neither tested nor guaranteed.

#### 3.8.1 Example 1

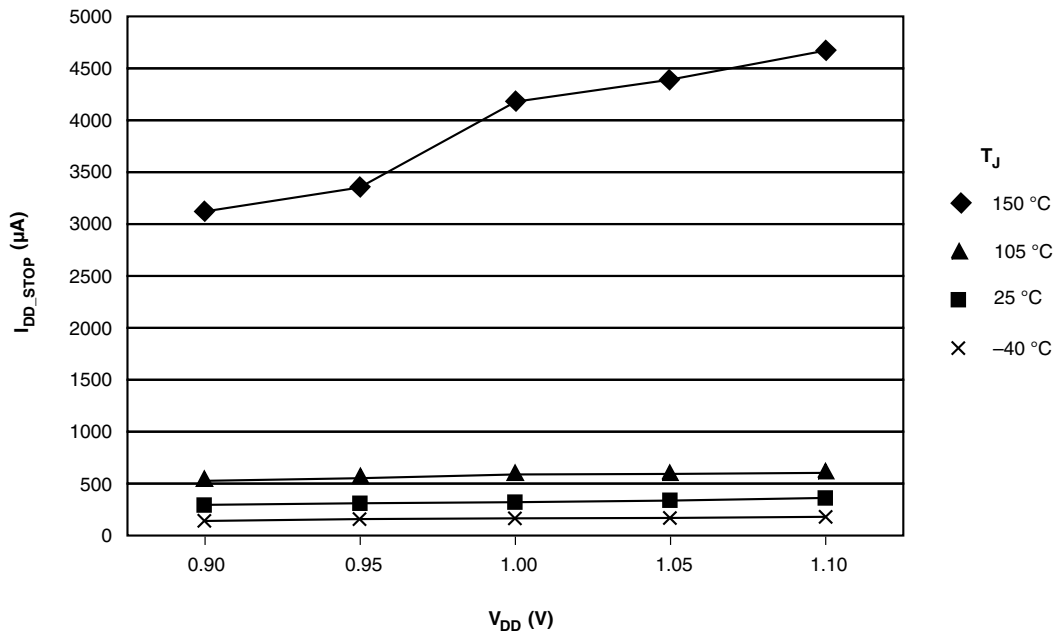
This is an example of an operating behavior that includes a typical value:

## Ratings

Symbol	Description	Min.	Typ.	Max.	Unit
$I_{WP}$	Digital I/O weak pullup/pulldown current	10	70	130	$\mu\text{A}$

### 3.8.2 Example 2

This is an example of a chart that shows typical values for various voltage and temperature conditions:



## 3.9 Typical value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

Symbol	Description	Value	Unit
$T_A$	Ambient temperature	25	$^{\circ}\text{C}$
$V_{DD}$	3.3 V supply voltage	3.3	V

## 4 Ratings

## 4.1 Thermal handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
T <sub>STG</sub>	Storage temperature	-55	150	°C	1
T <sub>SDR</sub>	Solder temperature, lead-free	—	260	°C	2
	Solder temperature, leaded	—	245		

1. Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
2. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

## 4.2 Moisture handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
MSL	Moisture sensitivity level	—	3	—	1

1. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

## 4.3 ESD handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
V <sub>HBM</sub>	Electrostatic discharge voltage, human body model	-2000	+2000	V	1
V <sub>CDM</sub>	Electrostatic discharge voltage, charged-device model	-500	+500	V	2
I <sub>LAT</sub>	Latch-up current at ambient temperature of 85°C	-100	+100	mA	

1. Determined according to JEDEC Standard JESD22-A114, *Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)*.
2. Determined according to JEDEC Standard JESD22-C101, *Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components*.

## 4.4 Voltage and current operating ratings

Symbol	Description	Min.	Max.	Unit
V <sub>DD</sub>	Digital supply voltage	-0.3	3.8	V
I <sub>DD</sub>	Digital supply current	—	185	mA
V <sub>DIO</sub>	Digital input voltage (except RESET, EXTAL, and XTAL)	-0.3	5.5	V

Table continues on the next page...

## General

Symbol	Description	Min.	Max.	Unit
V <sub>AIO</sub>	Analog, RESET, EXTAL, and XTAL input voltage	-0.3	V <sub>DD</sub> + 0.3	V
I <sub>D</sub>	Instantaneous maximum current single pin limit (applies to all port pins)	-25	25	mA
V <sub>DDA</sub>	Analog supply voltage	V <sub>DD</sub> - 0.3	V <sub>DD</sub> + 0.3	V
V <sub>USB_DP</sub>	USB_DP input voltage	-0.3	3.63	V
V <sub>USB_DM</sub>	USB_DM input voltage	-0.3	3.63	V
V <sub>REGIN</sub>	USB regulator input	-0.3	6.0	V
V <sub>BAT</sub>	RTC battery supply voltage	-0.3	3.8	V

## 5 General

### 5.1 Nonswitching electrical specifications

#### 5.1.1 Voltage and current operating requirements

Table 1. Voltage and current operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V <sub>DD</sub>	Supply voltage	1.71	3.6	V	
V <sub>DDA</sub>	Analog supply voltage	1.71	3.6	V	
V <sub>DD</sub> - V <sub>DDA</sub>	V <sub>DD</sub> -to-V <sub>DDA</sub> differential voltage	-0.1	0.1	V	
V <sub>SS</sub> - V <sub>SSA</sub>	V <sub>SS</sub> -to-V <sub>SSA</sub> differential voltage	-0.1	0.1	V	
V <sub>BAT</sub>	RTC battery supply voltage	1.71	3.6	V	
V <sub>IH</sub>	Input high voltage <ul style="list-style-type: none"><li>2.7 V ≤ V<sub>DD</sub> ≤ 3.6 V</li><li>1.7 V ≤ V<sub>DD</sub> ≤ 2.7 V</li></ul>	0.7 × V <sub>DD</sub>	—	V	
		0.75 × V <sub>DD</sub>	—	V	
V <sub>IL</sub>	Input low voltage <ul style="list-style-type: none"><li>2.7 V ≤ V<sub>DD</sub> ≤ 3.6 V</li><li>1.7 V ≤ V<sub>DD</sub> ≤ 2.7 V</li></ul>	—	0.35 × V <sub>DD</sub>	V	
		—	0.3 × V <sub>DD</sub>	V	
V <sub>HYS</sub>	Input hysteresis	0.06 × V <sub>DD</sub>	—	V	

Table continues on the next page...

**Table 1. Voltage and current operating requirements (continued)**

Symbol	Description	Min.	Max.	Unit	Notes
$I_{IC}$	DC injection current — single pin <ul style="list-style-type: none"> <li><math>V_{IN} &lt; V_{SS}</math></li> </ul>	0	-0.2	mA	1
	DC injection current — total MCU limit, includes sum of all stressed pins <ul style="list-style-type: none"> <li><math>V_{IN} &lt; V_{SS}</math></li> </ul>	0	-5	mA	1
$V_{RAM}$	$V_{DD}$ voltage required to retain RAM	1.2	—	V	
$V_{RFVBAT}$	$V_{BAT}$ voltage required to retain the VBAT register file	TBD	—	V	

1. All functional non-supply pins are internally clamped to  $V_{SS}$ , and induce an injection current when  $V_{IN}$  is less than  $V_{SS}$ . The  $I_{IC}$  maximum operating requirement should not be exceeded. If this requirement cannot be met, the input must be current limited to the value specified.

## 5.1.2 LVD and POR operating requirements

**Table 2.  $V_{DD}$  supply LVD and POR operating requirements**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$V_{POR}$	Falling VDD POR detect voltage	TBD	1.1	TBD	V	
$V_{LVDH}$	Falling low-voltage detect threshold — high range (LVDV=01)	TBD	2.56	TBD	V	
$V_{LW1H}$ $V_{LW2H}$ $V_{LW3H}$ $V_{LW4H}$	Low-voltage warning thresholds — high range <ul style="list-style-type: none"> <li>Level 1 falling (LVWV=00)</li> <li>Level 2 falling (LVWV=01)</li> <li>Level 3 falling (LVWV=10)</li> <li>Level 4 falling (LVWV=11)</li> </ul>	TBD	2.70	TBD	V	1
		TBD	2.80	TBD	V	
		TBD	2.90	TBD	V	
		TBD	3.00	TBD	V	
$V_{HYSH}$	Low-voltage inhibit reset/recover hysteresis — high range		60		mV	
$V_{LVDL}$	Falling low-voltage detect threshold — low range (LVDV=00)	TBD	1.60	TBD	V	
$V_{LW1L}$ $V_{LW2L}$ $V_{LW3L}$ $V_{LW4L}$	Low-voltage warning thresholds — low range <ul style="list-style-type: none"> <li>Level 1 falling (LVWV=00)</li> <li>Level 2 falling (LVWV=01)</li> <li>Level 3 falling (LVWV=10)</li> <li>Level 4 falling (LVWV=11)</li> </ul>	TBD	1.80	TBD	V	1
		TBD	1.90	TBD	V	
		TBD	2.00	TBD	V	
		TBD	2.10	TBD	V	
$V_{HYSL}$	Low-voltage inhibit reset/recover hysteresis — low range		40		mV	
$V_{BG}$	Bandgap voltage reference	TBD	1.00	TBD	V	
$t_{LPO}$	Internal low power oscillator period factory trimmed	TBD	1000	TBD	$\mu$ s	

## General

1. Rising thresholds are falling threshold + hysteresis voltage

**Table 3. VBAT power operating requirements**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V <sub>POR_VBAT</sub>	Falling VBAT supply POR detect voltage	TBD	1.1	TBD	V	

## 5.1.3 Voltage and current operating behaviors

**Table 4. Voltage and current operating behaviors**

Symbol	Description	Min.	Max.	Unit	Notes
V <sub>OH</sub>	Output high voltage — high drive strength				
	• 2.7 V ≤ V <sub>DD</sub> ≤ 3.6 V, I <sub>OH</sub> = -10mA	V <sub>DD</sub> - 0.5	—	V	
	• 1.71 V ≤ V <sub>DD</sub> ≤ 2.7 V, I <sub>OH</sub> = -3mA	V <sub>DD</sub> - 0.5	—	V	
	Output high voltage — low drive strength				
• 2.7 V ≤ V <sub>DD</sub> ≤ 3.6 V, I <sub>OH</sub> = -2mA	V <sub>DD</sub> - 0.5	—	V		
• 1.71 V ≤ V <sub>DD</sub> ≤ 2.7 V, I <sub>OH</sub> = -0.6mA	V <sub>DD</sub> - 0.5	—	V		
I <sub>OHT</sub>	Output high current total for all ports	—	100	mA	
V <sub>OL</sub>	Output low voltage — high drive strength				
	• 2.7 V ≤ V <sub>DD</sub> ≤ 3.6 V, I <sub>OL</sub> = 10mA	—	0.5	V	
	• 1.71 V ≤ V <sub>DD</sub> ≤ 2.7 V, I <sub>OL</sub> = 3mA	—	0.5	V	
	Output low voltage — low drive strength				
• 2.7 V ≤ V <sub>DD</sub> ≤ 3.6 V, I <sub>OL</sub> = 2mA	—	0.5	V		
• 1.71 V ≤ V <sub>DD</sub> ≤ 2.7 V, I <sub>OL</sub> = 0.6mA	—	0.5	V		
I <sub>OLT</sub>	Output low current total for all ports	—	100	mA	
I <sub>IN</sub>	Input leakage current (per pin)	—	1	μA	1
I <sub>OZ</sub>	Hi-Z (off-state) leakage current (per pin)	—	1	μA	
R <sub>PU</sub>	Internal pullup resistors	30	50	kΩ	2
R <sub>PD</sub>	Internal pulldown resistors	30	50	kΩ	3

1. Measured at V<sub>DD</sub>=3.6V
2. Measured at V<sub>DD</sub> supply voltage = V<sub>DD</sub> min and V<sub>input</sub> = V<sub>SS</sub>
3. Measured at V<sub>DD</sub> supply voltage = V<sub>DD</sub> min and V<sub>input</sub> = V<sub>DD</sub>

## 5.1.4 Power mode transition operating behaviors

All specifications except t<sub>POR</sub>, and VLLS<sub>x</sub>→RUN recovery times in the following table assume this clock configuration:

- CPU and system clocks = 100 MHz
- Bus and FlexBus clocks = 50 MHz
- Flash clock = 25 MHz

**Table 5. Power mode transition operating behaviors**

Symbol	Description	Min.	Max.	Unit	Notes
$t_{POR}$	After a POR event, amount of time from the point $V_{DD}$ reaches 1.8V to execution of the first instruction across the operating temperature range of the chip.	—	300	$\mu$ s	1
	RUN $\rightarrow$ VLLS1 $\rightarrow$ RUN				
	• RUN $\rightarrow$ VLLS1	—	4.1	$\mu$ s	
	• VLLS1 $\rightarrow$ RUN	—	123.8	$\mu$ s	
	RUN $\rightarrow$ VLLS2 $\rightarrow$ RUN				
	• RUN $\rightarrow$ VLLS2	—	4.1	$\mu$ s	
	• VLLS2 $\rightarrow$ RUN	—	49.3	$\mu$ s	
	RUN $\rightarrow$ VLLS3 $\rightarrow$ RUN				
	• RUN $\rightarrow$ VLLS3	—	4.1	$\mu$ s	
	• VLLS3 $\rightarrow$ RUN	—	49.2	$\mu$ s	
	RUN $\rightarrow$ LLS $\rightarrow$ RUN				
	• RUN $\rightarrow$ LLS	—	4.1	$\mu$ s	
	• LLS $\rightarrow$ RUN	—	5.9	$\mu$ s	
	RUN $\rightarrow$ STOP $\rightarrow$ RUN				
	• RUN $\rightarrow$ STOP	—	4.1	$\mu$ s	
	• STOP $\rightarrow$ RUN	—	4.2	$\mu$ s	
	RUN $\rightarrow$ VLPS $\rightarrow$ RUN				
	• RUN $\rightarrow$ VLPS	—	4.1	$\mu$ s	
	• VLPS $\rightarrow$ RUN	—	5.8	$\mu$ s	

1. Normal boot (FTFL\_OPT[LPBOOT]=1)

## 5.1.5 Power consumption operating behaviors

**Table 6. Power consumption operating behaviors**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$I_{DDA}$	Analog supply current	—	—	TBD	mA	1

Table continues on the next page...

**Table 6. Power consumption operating behaviors (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I <sub>DD_RUN</sub>	Run mode current — all peripheral clocks disabled, code executing from flash <ul style="list-style-type: none"> <li>• @ 1.8V</li> <li>• @ 3.0V</li> </ul>	— —	40 42	TBD TBD	mA mA	2
I <sub>DD_RUN</sub>	Run mode current — all peripheral clocks enabled, code executing from flash <ul style="list-style-type: none"> <li>• @ 1.8V</li> <li>• @ 3.0V</li> </ul>	— —	55 56	TBD TBD	mA mA	3
I <sub>DD_RUN_M AX</sub>	Run mode current — all peripheral clocks enabled and peripherals active, code executing from flash <ul style="list-style-type: none"> <li>• @ 1.8V</li> <li>• @ 3.0V</li> </ul>	— —	85 85	TBD TBD	mA mA	4
I <sub>DD_WAIT</sub>	Wait mode high frequency current at 3.0 V — all peripheral clocks disabled	—	35	TBD	mA	2
I <sub>DD_WAIT</sub>	Wait mode reduced frequency current at 3.0 V — all peripheral clocks disabled	—	15	TBD	mA	5
I <sub>DD_STOP</sub>	Stop mode current at 3.0 V	—	0.4	TBD	mA	
I <sub>DD_VLPR</sub>	Very-low-power run mode current at 3.0 V — all peripheral clocks disabled	—	1.25	TBD	mA	6
I <sub>DD_VLPR</sub>	Very-low-power run mode current at 3.0 V — all peripheral clocks enabled	—	TBD	TBD	mA	7
I <sub>DD_VLPW</sub>	Very-low-power wait mode current at 3.0 V	—	1.05	TBD	mA	8
I <sub>DD_VLPS</sub>	Very-low-power stop mode current at 3.0 V	—	50	TBD	μA	
I <sub>DD_LLS</sub>	Low leakage stop mode current at 3.0 V	—	12	TBD	μA	
I <sub>DD_VLLS3</sub>	Very low-leakage stop mode 3 current at 3.0 V <ul style="list-style-type: none"> <li>• 128KB RAM devices</li> <li>• 64KB RAM devices</li> </ul>	— —	8 6	TBD TBD	μA μA	
I <sub>DD_VLLS2</sub>	Very low-leakage stop mode 2 current at 3.0 V	—	4	TBD	μA	
I <sub>DD_VLLS1</sub>	Very low-leakage stop mode 1 current at 3.0 V	—	2	TBD	μA	
I <sub>DD_VBAT</sub>	Average current when CPU is not accessing RTC registers at 3.0 V	—	550	TBD	nA	9

1. The analog supply current is the sum of the active or disabled current for each of the analog modules on the device. See each module's specification for its supply current.
2. 100MHz core and system clock, 50MHz bus and FlexBus clock, and 25MHz flash clock. MCG configured for FEI mode. All peripheral clocks disabled.
3. 100MHz core and system clock, 50MHz bus and FlexBus clock, and 25MHz flash clock. MCG configured for FEI mode. All peripheral clocks enabled, but peripherals are not in active operation.
4. 100MHz core and system clock, 50MHz bus and FlexBus clock, and 25MHz flash clock. MCG configured for FEI mode. All peripheral clocks enabled, and peripherals are in active operation.
5. 25MHz core and system clock, 25MHz bus clock, and 12.5MHz FlexBus and flash clock. MCG configured for FEI mode.

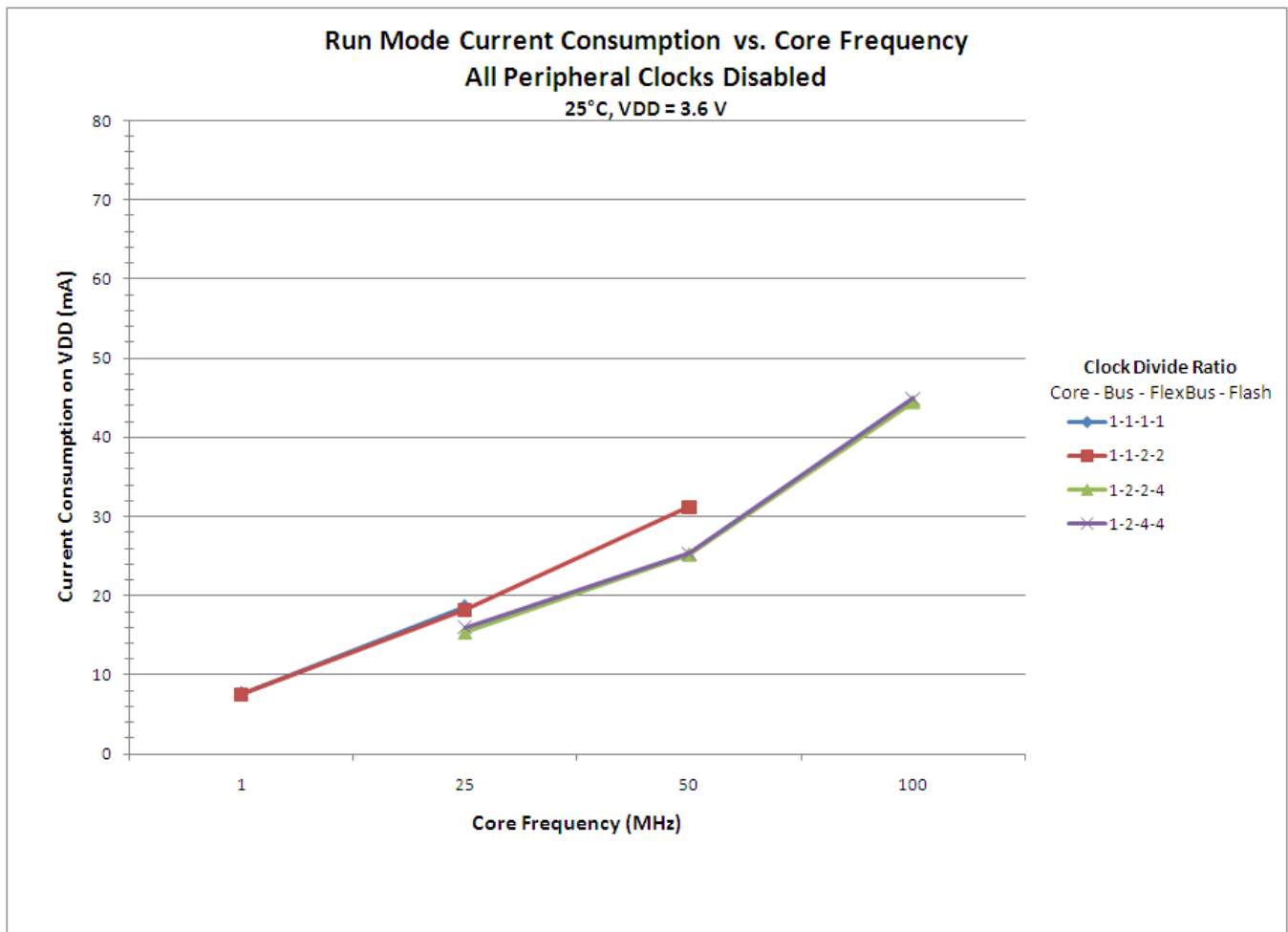


6. 2 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for fast IRCLK mode. All peripheral clocks disabled. Code executing from flash.
7. 2 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for fast IRCLK mode. All peripheral clocks enabled but peripherals are not in active operation. Code executing from flash.
8. 2 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for fast IRCLK mode. All peripheral clocks disabled.
9. Includes 32kHz oscillator current and RTC operation.

### 5.1.5.1 Diagram: Typical IDD\_RUN operating behavior

The following data was measured under these conditions:

- MCG in FEI mode (39.0625 kHz IRC), except for 1 MHz core (FBE)
- All peripheral clocks disabled except FTFI
- LVD disabled, USB regulator disabled
- No GPIOs toggled
- Code execution from flash

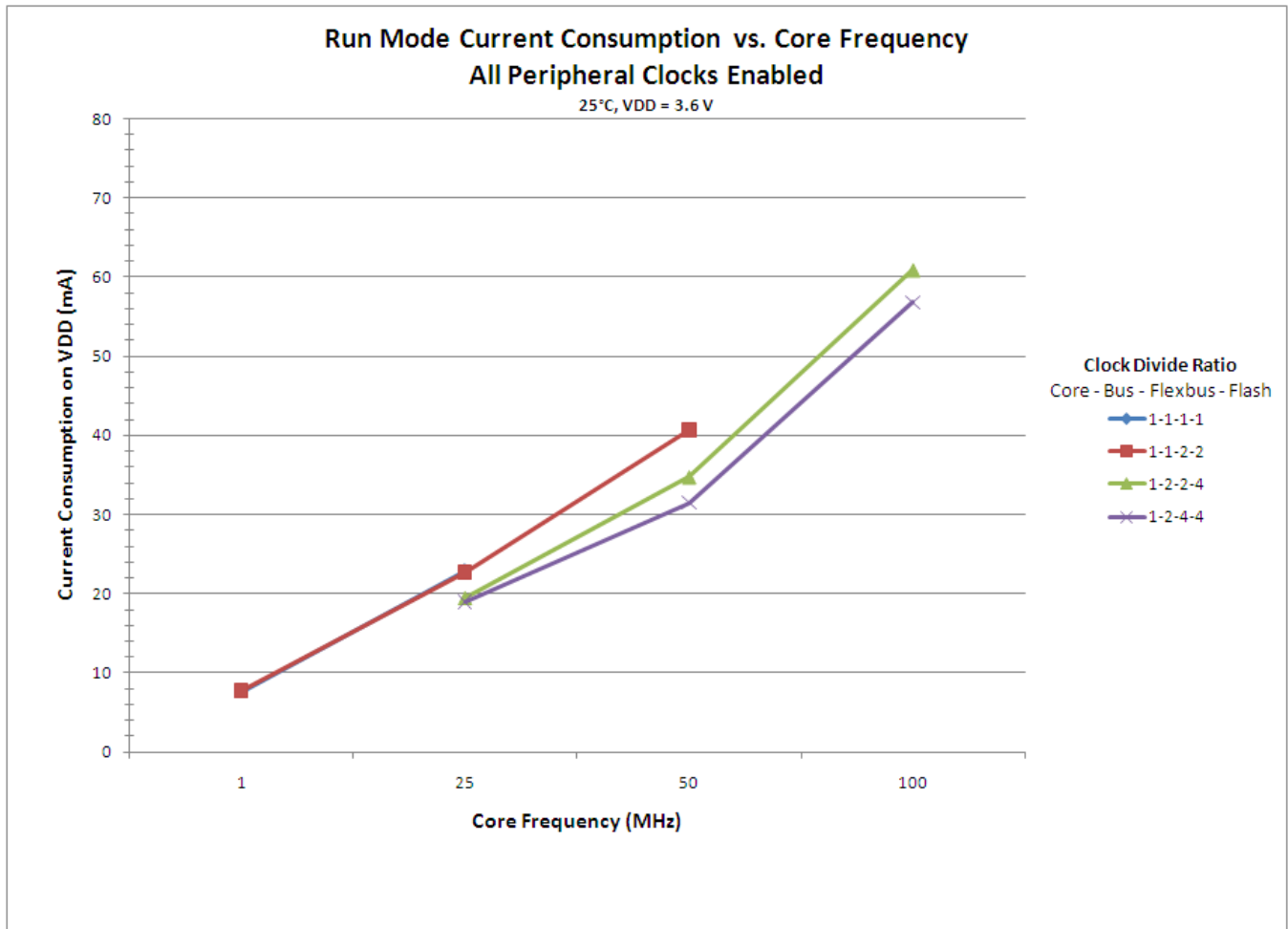


**Figure 1. Run mode supply current vs. core frequency — all peripheral clocks disabled**

The following data was measured under these conditions:

## General

- MCG in FEI mode (39.0625 kHz IRC), except for 1 MHz core (FBE)
- All peripheral clocks enabled but peripherals are not in active operation
- LVD disabled, USB regulator disabled
- No GPIOs toggled
- Code execution from flash



**Figure 2. Run mode supply current vs. core frequency — all peripheral clocks enabled**

## 5.1.6 EMC radiated emissions operating behaviors

Table 7. EMC radiated emissions operating behaviors

Symbol	Description	Frequency band (MHz)	Typ.	Unit	Notes
V <sub>RE1</sub>	Radiated emissions voltage, band 1	0.15–50	TBD	dB $\mu$ V	1, 2
V <sub>RE2</sub>	Radiated emissions voltage, band 2	50–150	TBD		
V <sub>RE3</sub>	Radiated emissions voltage, band 3	150–500	TBD		
V <sub>RE4</sub>	Radiated emissions voltage, band 4	500–1000	TBD		
V <sub>RE_IEC_SAE</sub>	IEC and SAE level	0.15–1000	TBD	—	2, 3

1. Determined according to IEC Standard 61967-1, *Integrated Circuits - Measurement of Electromagnetic Emissions, 150 kHz to 1 GHz Part 1: General Conditions and Definitions*, IEC Standard 61967-2, *Integrated Circuits - Measurement of Electromagnetic Emissions, 150 kHz to 1 GHz Part 2: Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method*, and SAE Standard J1752-3, *Measurement of Radiated Emissions from Integrated Circuits—TEM/Wideband TEM (GTEM) Cell Method*.
2. V<sub>DD</sub> = 3 V, T<sub>A</sub> = 25 °C, f<sub>OSC</sub> = 12 MHz (crystal), f<sub>SYS</sub> = 96 MHz
3. Specified according to Annex D of IEC Standard 61967-2, *Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method*, and Appendix D of SAE Standard J1752-3, *Measurement of Radiated Emissions from Integrated Circuits—TEM/Wideband TEM (GTEM) Cell Method*.

## 5.1.7 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

1. Go to <http://www.freescale.com>.
2. Perform a keyword search for “EMC design.”

## 5.1.8 Capacitance attributes

Table 8. Capacitance attributes

Symbol	Description	Min.	Max.	Unit
C <sub>IN_A</sub>	Input capacitance: analog pins	—	7	pF
C <sub>IN_D</sub>	Input capacitance: digital pins	—	7	pF

## 5.2 Switching specifications

## 5.2.1 Device clock specifications

Symbol	Description	Min.	Max.	Unit	Notes
Normal run mode					
f <sub>SYS</sub>	System and core clock	—	100	MHz	
f <sub>SYS_USB</sub>	System and core clock when USB in operation	20	—	MHz	
f <sub>BUS</sub>	Bus clock	—	50	MHz	
FB_CLK	FlexBus clock	—	50	MHz	
f <sub>FLASH</sub>	Flash clock	—	25	MHz	
VLPR mode					
f <sub>SYS</sub>	System and core clock	—	2	MHz	
f <sub>BUS</sub>	Bus clock	—	2	MHz	
FB_CLK	FlexBus clock	—	2	MHz	
f <sub>FLASH</sub>	Flash clock	—	1	MHz	

## 5.2.2 General switching specifications

These general purpose specifications apply to all signals configured for GPIO, UART, CAN, CMT, IEEE 1588 timer, and I<sup>2</sup>C signals.

Symbol	Description	Min.	Max.	Unit	Notes
	GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path	1.5	—	Bus clock cycles	1
	GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter enabled) — Asynchronous path	100	—	ns	2
	GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter disabled) — Asynchronous path	16	—	ns	2
	External reset pulse width (digital glitch filter disabled)	TBD	—		
	Mode select (E <sub>ZP_CS</sub> ) hold time after reset deassertion	2	—	Bus clock cycles	
	Port rise and fall time (high drive strength)				3
	<ul style="list-style-type: none"> <li>• Slew disabled</li> <li>• Slew enabled</li> </ul>	— —	12 36	ns ns	
	Port rise and fall time (low drive strength)				4
	<ul style="list-style-type: none"> <li>• Slew disabled</li> <li>• Slew enabled</li> </ul>	— —	32 36	ns ns	

1. The greater synchronous and asynchronous timing must be met.
2. This is the shortest pulse that is guaranteed to be recognized.
3. 75pF load

## 4. 15pF load

## 5.3 Thermal specifications

### 5.3.1 Thermal operating requirements

Table 9. Thermal operating requirements

Symbol	Description	Min.	Max.	Unit
$T_J$	Die junction temperature	-40	125	°C
$T_A$	Ambient temperature	-40	105	°C

### 5.3.2 Thermal attributes

Board type	Symbol	Description	144 LQFP	144 MAPBG	81 MAPBG	80 LQFP	Unit	Notes
Single-layer (1s)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	52	50	TBD	TBD	°C/W	1
Four-layer (2s2p)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	44	30	TBD	TBD	°C/W	1
Single-layer (1s)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./min. air speed)	43	41	TBD	TBD	°C/W	1
Four-layer (2s2p)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./min. air speed)	38	27	TBD	TBD	°C/W	1
—	$R_{\theta JB}$	Thermal resistance, junction to board	33	17	TBD	TBD	°C/W	2
—	$R_{\theta JC}$	Thermal resistance, junction to case	11	10	TBD	TBD	°C/W	3
—	$\Psi_{JT}$	Thermal characterization parameter, junction to package top outside center (natural convection)	2	2	TBD	TBD	°C/W	4

1. Determined according to JEDEC Standard JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions—Natural Convection (Still Air)*, or EIA/JEDEC Standard JESD51-6, *Integrated Circuit Thermal Test Method Environmental Conditions—Forced Convection (Moving Air)*.

## 6 Peripheral operating requirements and behaviors

All digital I/O switching characteristics assume:

1. output pins

Peripheral operating requirements and behaviors

- have  $C_L=30\text{pF}$  loads,
- are configured for fast slew rate ( $\text{PORTx\_PCRn[SRE]}=0$ ), and
- are configured for high drive strength ( $\text{PORTx\_PCRn[DSE]}=1$ )

2. input pins

- have their passive filter disabled ( $\text{PORTx\_PCRn[PFE]}=0$ )

## 6.1 Core modules

### 6.1.1 Debug trace timing specifications

Table 10. Debug trace operating behaviors

Symbol	Description	Min.	Max.	Unit
$T_{cyc}$	Clock period	Frequency dependent		MHz
$T_{wl}$	Low pulse width	2	—	ns
$T_{wh}$	High pulse width	2	—	ns
$T_r$	Clock and data rise time	—	3	ns
$T_f$	Clock and data fall time	—	3	ns
$T_s$	Data setup	3	—	ns
$T_h$	Data hold	2	—	ns

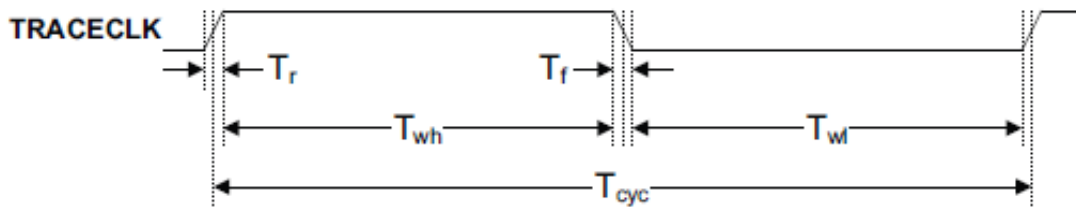


Figure 3. TRACE\_CLKOUT specifications

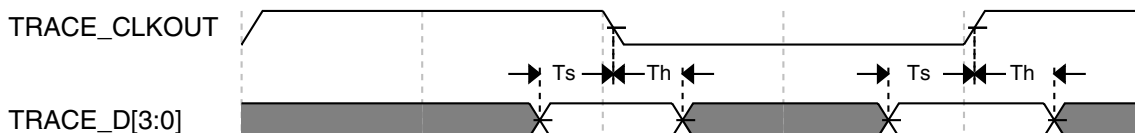


Figure 4. Trace data specifications

## 6.1.2 JTAG electricals

**Table 11. JTAG limited voltage range electricals**

Symbol	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
J1	TCLK frequency of operation <ul style="list-style-type: none"> <li>• Boundary Scan</li> <li>• JTAG and CJTAG</li> <li>• Serial Wire Debug</li> </ul>	0 0 0	10 25 50	MHz
J2	TCLK cycle period	1/J1	—	ns
J3	TCLK clock pulse width <ul style="list-style-type: none"> <li>• Boundary Scan</li> <li>• JTAG and CJTAG</li> <li>• Serial Wire Debug</li> </ul>	50 20 10	— —	ns
J4	TCLK rise and fall times	—	3	ns
J5	Boundary scan input data setup time to TCLK rise	20	—	ns
J6	Boundary scan input data hold time after TCLK rise	0	—	ns
J7	TCLK low to boundary scan output data valid	—	25	ns
J8	TCLK low to boundary scan output high-Z	—	25	ns
J9	TMS, TDI input data setup time to TCLK rise	8	—	ns
J10	TMS, TDI input data hold time after TCLK rise	1	—	ns
J11	TCLK low to TDO data valid	—	17	ns
J12	TCLK low to TDO high-Z	—	17	ns
J13	TRST assert time	100	—	ns
J14	TRST setup time (negation) to TCLK high	8	—	ns

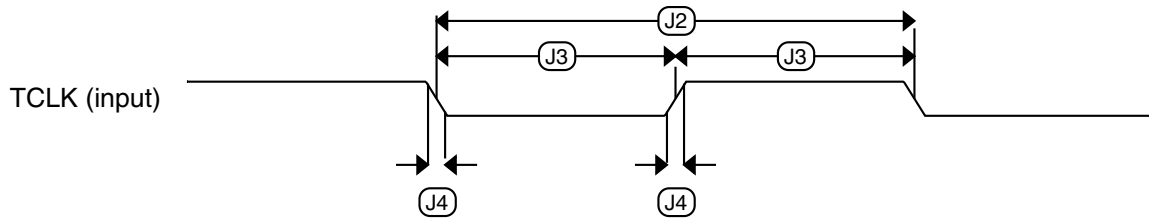
**Table 12. JTAG full voltage range electricals**

Symbol	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
J1	TCLK frequency of operation <ul style="list-style-type: none"> <li>• Boundary Scan</li> <li>• JTAG and CJTAG</li> <li>• Serial Wire Debug</li> </ul>	0 0 0	10 20 40	MHz
J2	TCLK cycle period	1/J1	—	ns

Table continues on the next page...

**Table 12. JTAG full voltage range electricals (continued)**

Symbol	Description	Min.	Max.	Unit
J3	TCLK clock pulse width <ul style="list-style-type: none"> <li>• Boundary Scan</li> <li>• JTAG and CJTAG</li> <li>• Serial Wire Debug</li> </ul>	50 25 12.5	—	ns
J4	TCLK rise and fall times	—	3	ns
J5	Boundary scan input data setup time to TCLK rise	20	—	ns
J6	Boundary scan input data hold time after TCLK rise	0	—	ns
J7	TCLK low to boundary scan output data valid	—	25	ns
J8	TCLK low to boundary scan output high-Z	—	25	ns
J9	TMS, TDI input data setup time to TCLK rise	8	—	ns
J10	TMS, TDI input data hold time after TCLK rise	1.4	—	ns
J11	TCLK low to TDO data valid	—	22.1	ns
J12	TCLK low to TDO high-Z	—	22.1	ns
J13	$\overline{\text{TRST}}$ assert time	100	—	ns
J14	$\overline{\text{TRST}}$ setup time (negation) to TCLK high	8	—	ns



**Figure 5. Test clock input timing**



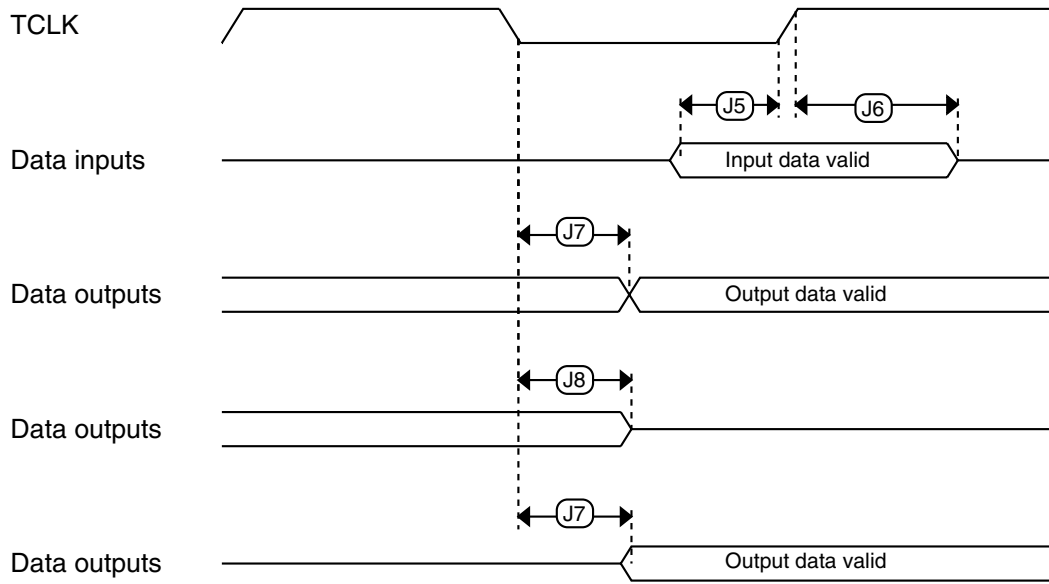


Figure 6. Boundary scan (JTAG) timing

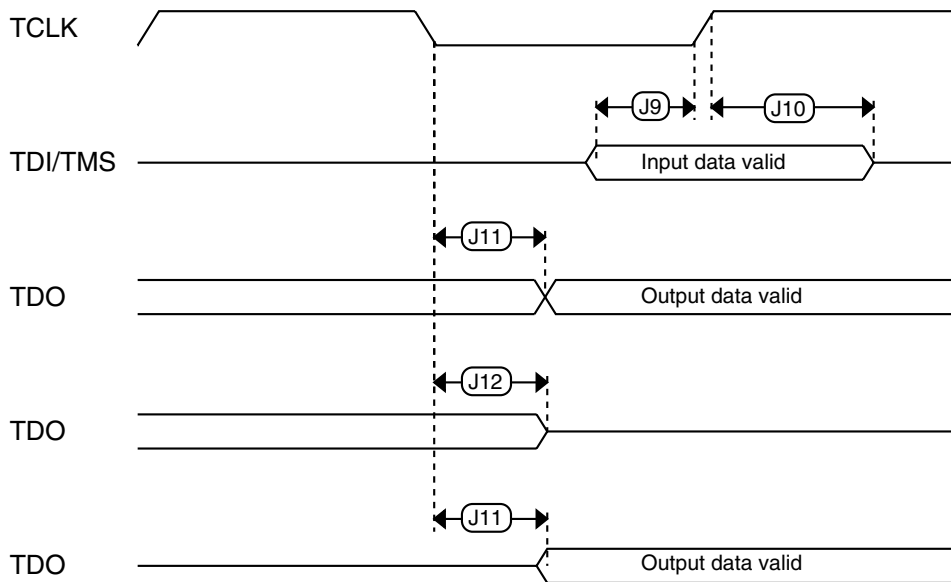
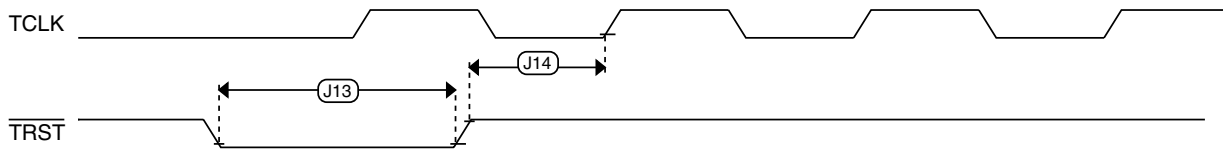


Figure 7. Test Access Port timing

Figure 8.  $\overline{\text{TRST}}$  timing

## 6.2 System modules

There are no specifications necessary for the device's system modules.

## 6.3 Clock modules

### 6.3.1 MCG specifications

Table 13. MCG specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$f_{\text{ints\_ft}}$	Internal reference frequency (slow clock) — factory trimmed at nominal VDD and 25°C	—	32.768	—	kHz	
$f_{\text{ints\_t}}$	Internal reference frequency (slow clock) — user trimmed	31.25	—	39.0625	kHz	
$I_{\text{ints}}$	Internal reference (slow clock) current	—	TBD	—	$\mu\text{A}$	
$t_{\text{refsts}}$	Internal reference (slow clock) startup time	—	TBD	4	$\mu\text{s}$	
$\Delta f_{\text{dco\_res\_t}}$	Resolution of trimmed DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM	—	$\pm 0.1$	$\pm 0.3$	$\%f_{\text{dco}}$	1
$\Delta f_{\text{dco\_res\_t}}$	Resolution of trimmed DCO output frequency at fixed voltage and temperature — using SCTRIM only	—	$\pm 0.2$	$\pm 0.5$	$\%f_{\text{dco}}$	1
$\Delta f_{\text{dco\_t}}$	Total deviation of trimmed average DCO output frequency over voltage and temperature	—	+ 0.5 - 1.0	$\pm 3.5$	$\%f_{\text{dco}}$	1
$\Delta f_{\text{dco\_t}}$	Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70°C	—	$\pm 0.5$	$\pm \text{TBD}$	$\%f_{\text{dco}}$	1
$f_{\text{intf\_ft}}$	Internal reference frequency (fast clock) — factory trimmed at nominal VDD and 25°C	3.4	—	4	MHz	
$f_{\text{intf\_t}}$	Internal reference frequency (fast clock) — user trimmed	3	—	5	MHz	

Table continues on the next page...

Table 13. MCG specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes	
$I_{intf}$	Internal reference (fast clock) current	—	TBD	—	$\mu\text{A}$		
$t_{irefstf}$	Internal reference startup time (fast clock)	—	TBD	TBD	$\mu\text{s}$		
$f_{loc\_low}$	Loss of external clock minimum frequency — RANGE = 00	$(3/5) \times f_{ints\_t}$	—	—	kHz		
$f_{loc\_high}$	Loss of external clock minimum frequency — RANGE = 01, 10, or 11	$(16/5) \times f_{ints\_t}$	—	—	kHz		
FLL							
$f_{fill\_ref}$	FLL reference frequency range	31.25	—	39.0625	kHz		
$f_{dco}$	DCO output frequency range	Low range (DRS=00) $640 \times f_{fill\_ref}$	20	20.97	25	MHz	2, 3
		Mid range (DRS=01) $1280 \times f_{fill\_ref}$	40	41.94	50	MHz	
		Mid-high range (DRS=10) $1920 \times f_{fill\_ref}$	60	62.91	75	MHz	
		High range (DRS=11) $2560 \times f_{fill\_ref}$	80	83.89	100	MHz	
$f_{dco\_t\_DMX3}$ 2	DCO output frequency	Low range (DRS=00) $732 \times f_{fill\_ref}$	—	23.99	—	MHz	4, 5
		Mid range (DRS=01) $1464 \times f_{fill\_ref}$	—	47.97	—	MHz	
		Mid-high range (DRS=10) $2197 \times f_{fill\_ref}$	—	71.99	—	MHz	
		High range (DRS=11) $2929 \times f_{fill\_ref}$	—	95.98	—	MHz	
$J_{cyc\_fill}$	FLL period jitter	—	TBD	TBD	ps	6	
$J_{acc\_fill}$	FLL accumulated jitter of DCO output over a 1 $\mu\text{s}$ time window	—	TBD	TBD	ps	6	
$t_{fill\_acquire}$	FLL target frequency acquisition time	—	—	1	ms	7	
PLL							
$f_{vco}$	VCO operating frequency	48.0	—	100	MHz		
$I_{pll}$	PLL operating current • PLL @ 96 MHz ( $f_{osc\_hi\_1}$ =8MHz, $f_{pll\_ref}$ =2MHz, VDIV multiplier=48)	—	950	—	$\mu\text{A}$	8	
$f_{pll\_ref}$	PLL reference frequency range	2.0	—	4.0	MHz		
$J_{cyc\_pll}$	PLL period jitter	—	400	—	ps	9, 10	
$J_{acc\_pll}$	PLL accumulated jitter over 1 $\mu\text{s}$ window	—	TBD	—	ps	9, 10	

Table continues on the next page...

**Table 13. MCG specifications (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
D <sub>lock</sub>	Lock entry frequency tolerance	± 1.49	—	± 2.98	%	
D <sub>unl</sub>	Lock exit frequency tolerance	± 4.47	—	± 5.97	%	
t <sub>pll_lock</sub>	Lock detector detection time	—	—	0.15 + 1075(1/ f <sub>pll_ref</sub> )	ms	11

1. This parameter is measured with the internal reference (slow clock) being used as a reference to the FLL (FEI clock mode).
2. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=0.
3. The resulting system clock frequencies should not exceed their maximum specified values. The DCO frequency deviation ( $\Delta f_{dco\_i}$ ) over voltage and temperature should be considered.
4. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=1.
5. The resulting clock frequency must not exceed the maximum specified clock frequency of the device.
6. This specification was obtained at TBD frequency.
7. This specification applies to any time the FLL reference source or reference divider is changed, trim value is changed, DMX32 bit is changed, DRS bits are changed, or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.
8. Excludes any oscillator currents that are also consuming power while PLL is in operation.
9. This specification was obtained using a Freescale developed PCB. PLL jitter is dependent on the noise characteristics of each PCB and results will vary.
10. This specification was obtained at internal frequency of TBD.
11. This specification applies to any time the PLL VCO divider or reference divider is changed, or changing from PLL disabled (BLPE, BLPI) to PLL enabled (PBE, PEE). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

## 6.3.2 Oscillator electrical specifications

This section provides the electrical characteristics of the module.

### 6.3.2.1 Oscillator DC electrical specifications

**Table 14. Oscillator DC electrical specifications**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V <sub>DD</sub>	Supply voltage	1.71	—	3.6	V	
I <sub>DDOSC</sub>	Supply current — low-power mode (HGO=0) <ul style="list-style-type: none"> <li>• 32 kHz</li> <li>• 4 MHz</li> <li>• 8 MHz</li> <li>• 16 MHz</li> <li>• 24 MHz</li> <li>• 32 MHz</li> </ul>	—	500	—	nA	1
		—	200	—	μA	
		—	300	—	μA	
		—	700	—	μA	
		—	1.2	—	mA	
		—	1.5	—	mA	

Table continues on the next page...

**Table 14. Oscillator DC electrical specifications (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I <sub>DDOSC</sub>	Supply current — high gain mode (HGO=1)					1
	• 32 kHz	—	25	—	μA	
	• 4 MHz	—	400	—	μA	
	• 8 MHz	—	800	—	μA	
	• 16 MHz	—	1.5	—	mA	
	• 24 MHz	—	3	—	mA	
	• 32 MHz	—	4	—	mA	
C <sub>x</sub>	EXTAL load capacitance	—	—	—		2, 3
C <sub>y</sub>	XTAL load capacitance	—	—	—		2, 3
R <sub>F</sub>	Feedback resistor — low-frequency, low-power mode (HGO=0)	—	—	—	MΩ	2, 4
	Feedback resistor — low-frequency, high-gain mode (HGO=1)	—	10	—	MΩ	
	Feedback resistor — high-frequency, low-power mode (HGO=0)	—	—	—	MΩ	
	Feedback resistor — high-frequency, high-gain mode (HGO=1)	—	1	—	MΩ	
R <sub>S</sub>	Series resistor — low-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — low-frequency, high-gain mode (HGO=1)	—	200	—	kΩ	
	Series resistor — high-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — high-frequency, high-gain mode (HGO=1)	—	0	—	kΩ	
V <sub>pp</sub> <sup>5</sup>	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1)	—	V <sub>DD</sub>	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1)	—	V <sub>DD</sub>	—	V	

1. V<sub>DD</sub>=3.3 V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3. C<sub>x</sub>,C<sub>y</sub> can be provided by using either the integrated capacitors or by using external components.
4. When low power mode is selected, R<sub>F</sub> is integrated and must not be attached externally.

## Peripheral operating requirements and behaviors

- The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other devices.

### 6.3.2.2 Oscillator frequency specifications

Table 15. Oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$f_{osc\_lo}$	Oscillator crystal or resonator frequency — low frequency mode (MCG_C2[RANGE]=00)	32	—	40	kHz	
$f_{osc\_hi\_1}$	Oscillator crystal or resonator frequency — high frequency mode (low range) (MCG_C2[RANGE]=01)	3	—	8	MHz	
$f_{osc\_hi\_2}$	Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x)	8	—	32	MHz	
$f_{ec\_extal}$	Input clock frequency (external clock mode)	—	—	50	MHz	1
$t_{dc\_extal}$	Input clock duty cycle (external clock mode)	40	50	60	%	
$t_{cst}$	Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0)	—	TBD	—	ms	2, 3
	Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1)	—	800	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0)	—	4	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1)	—	3	—	ms	

- Other frequency limits may apply when external clock is being used as a reference for the FLL or PLL.
- Proper PC board layout procedures must be followed to achieve specifications.
- Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG\_S register being set.

### 6.3.3 32kHz Oscillator Electrical Characteristics

This section describes the module electrical characteristics.

#### 6.3.3.1 32kHz oscillator DC electrical specifications

Table 16. 32kHz oscillator DC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
$V_{BAT}$	Supply voltage	1.71	—	3.6	V
$R_F$	Internal feedback resistor	—	100	—	M $\Omega$
$C_{para}$	Parasitical capacitance of EXTAL32 and XTAL32	—	2.5	—	pF

Table continues on the next page...

**Table 16. 32kHz oscillator DC electrical specifications (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit
$C_{load}$	Internal load capacitance (programmable)	—	15	—	pF
$V_{pp}$	Peak-to-peak amplitude of oscillation	—	0.6	—	V

### 6.3.3.2 32kHz oscillator frequency specifications

**Table 17. 32kHz oscillator frequency specifications**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$f_{osc\_lo}$	Oscillator crystal	—	32	—	kHz	
$t_{start}$	Crystal start-up time	—	1000	—	ms	1

1. Proper PC board layout procedures must be followed to achieve specifications.

## 6.4 Memories and memory interfaces

### 6.4.1 Flash (FTFL) electrical specifications

This section describes the electrical characteristics of the FTFL module.

#### 6.4.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

**Table 18. NVM program/erase timing specifications**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{hvpgm4}$	Longword Program high-voltage time	—	20	TBD	$\mu$ s	
$t_{hversscr}$	Sector Erase high-voltage time	—	20	100	ms	1
$t_{hversblk256k}$	Erase Block high-voltage time for 256 KB	—	160	800	ms	1

1. Maximum time based on expectations at cycling end-of-life.

**6.4.1.2 Flash timing specifications — commands****Table 19. Flash command timing specifications**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{rd1blk256k}$	Read 1s Block execution time • 256 KB data flash	—	—	1.4	ms	
$t_{rd1sec2k}$	Read 1s Section execution time (flash sector)	—	—	40	$\mu$ s	1
$t_{pgmchk}$	Program Check execution time	—	—	35	$\mu$ s	1
$t_{rdsrc}$	Read Resource execution time	—	—	35	$\mu$ s	1
$t_{pgm4}$	Program Longword execution time	—	50	TBD	$\mu$ s	
$t_{ersblk256k}$	Erase Flash Block execution time • 256 KB data flash	—	160	800	ms	2
$t_{ersscr}$	Erase Flash Sector execution time	—	20	100	ms	2
$t_{pgmsec512}$	Program Section execution time • 512 B flash	—	TBD	TBD	ms	
$t_{pgmsec1k}$	• 1 KB flash	—	TBD	TBD	ms	
$t_{pgmsec2k}$	• 2 KB flash	—	TBD	TBD	ms	
$t_{rd1all}$	Read 1s All Blocks execution time	—	—	2.8	ms	
$t_{rdonce}$	Read Once execution time	—	—	35	$\mu$ s	1
$t_{pgmonce}$	Program Once execution time	—	50	TBD	$\mu$ s	
$t_{ersall}$	Erase All Blocks execution time	—	320	1600	ms	2
$t_{vfykey}$	Verify Backdoor Access Key execution time	—	—	35	$\mu$ s	1
$t_{pgmpart256k}$	Program Partition for EEPROM execution time • 256 KB FlexNVM	—	175	TBD	ms	
$t_{setram32k}$	Set FlexRAM Function execution time: • 32 KB EEPROM backup	—	TBD	TBD	ms	
$t_{setram256k}$	• 256 KB EEPROM backup	—	TBD	TBD	ms	
Byte-write to FlexRAM for EEPROM operation						
$t_{eewr8bers}$	Byte-write to erased FlexRAM location execution time	—	100	TBD	$\mu$ s	3
$t_{eewr8b32k}$	Byte-write to FlexRAM execution time: • 32 KB EEPROM backup	—	TBD	TBD	ms	
$t_{eewr8b64k}$	• 64 KB EEPROM backup	—	TBD	1.5	ms	
$t_{eewr8b128k}$	• 128 KB EEPROM backup	—	TBD	TBD	ms	
$t_{eewr8b256k}$	• 256 KB EEPROM backup	—	TBD	2.5	ms	
Word-write to FlexRAM for EEPROM operation						

Table continues on the next page...



**Table 19. Flash command timing specifications (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{\text{eewr16bers}}$	Word-write to erased FlexRAM location execution time	—	100	TBD	$\mu\text{s}$	
$t_{\text{eewr16b32k}}$	Word-write to FlexRAM execution time: <ul style="list-style-type: none"> <li>• 32 KB EEPROM backup</li> <li>• 64 KB EEPROM backup</li> <li>• 128 KB EEPROM backup</li> <li>• 256 KB EEPROM backup</li> </ul>	—	TBD	TBD	ms	
$t_{\text{eewr16b64k}}$		—	TBD	1.5	ms	
$t_{\text{eewr16b128k}}$		—	TBD	TBD	ms	
$t_{\text{eewr16b256k}}$		—	TBD	2.5	ms	
Longword-write to FlexRAM for EEPROM operation						
$t_{\text{eewr32bers}}$	Longword-write to erased FlexRAM location execution time	—	200	TBD	$\mu\text{s}$	
$t_{\text{eewr32b32k}}$	Longword-write to FlexRAM execution time: <ul style="list-style-type: none"> <li>• 32 KB EEPROM backup</li> <li>• 64 KB EEPROM backup</li> <li>• 128 KB EEPROM backup</li> <li>• 256 KB EEPROM backup</li> </ul>	—	TBD	TBD	ms	
$t_{\text{eewr32b64k}}$		—	TBD	2.7	ms	
$t_{\text{eewr32b128k}}$		—	TBD	TBD	ms	
$t_{\text{eewr32b256k}}$		—	TBD	3.7	ms	

1. Assumes 25MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.
3. For byte-writes to an erased FlexRAM location, the aligned word containing the byte must be erased.

### 6.4.1.3 Flash (FTFL) current and power specifications

**Table 20. Flash (FTFL) current and power specifications**

Symbol	Description	Typ.	Unit
$I_{\text{DD\_PGM}}$	Worst case programming current in program flash	10	mA

### 6.4.1.4 Reliability specifications

**Table 21. NVM reliability specifications**

Symbol	Description	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
Program Flash						
$t_{\text{nvmpretp10k}}$	Data retention after up to 10 K cycles	5	TBD	—	years	2
$t_{\text{nvmpretp1k}}$	Data retention after up to 1 K cycles	10	TBD	—	years	2
$t_{\text{nvmpretp100}}$	Data retention after up to 100 cycles	15	TBD	—	years	2
$\eta_{\text{nvmcycp}}$	Cycling endurance	10 K	TBD	—	cycles	3
Data Flash						
$t_{\text{nvmdtd10k}}$	Data retention after up to 10 K cycles	5	TBD	—	years	2

Table continues on the next page...

**Table 21. NVM reliability specifications (continued)**

Symbol	Description	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
$t_{nvmretd1k}$	Data retention after up to 1 K cycles	10	TBD	—	years	2
$t_{nvmretd100}$	Data retention after up to 100 cycles	15	TBD	—	years	2
$n_{nvmcygd}$	Cycling endurance	10 K	TBD	—	cycles	3
FlexRAM as EEPROM						
$t_{nvmretee100}$	Data retention up to 100% of write endurance	5	TBD	—	years	2
$t_{nvmretee10}$	Data retention up to 10% of write endurance	10	TBD	—	years	2
$t_{nvmretee1}$	Data retention up to 1% of write endurance	15	TBD	—	years	2
	Write endurance					4
$n_{nvmwree16}$	• EEPROM backup to FlexRAM ratio = 16	35 K	TBD	—	writes	
$n_{nvmwree128}$	• EEPROM backup to FlexRAM ratio = 128	315 K	TBD	—	writes	
$n_{nvmwree512}$	• EEPROM backup to FlexRAM ratio = 512	1.27 M	TBD	—	writes	
$n_{nvmwree4k}$	• EEPROM backup to FlexRAM ratio = 4096	10 M	TBD	—	writes	
$n_{nvmwree32k}$	• EEPROM backup to FlexRAM ratio = 32,768	80 M	TBD	—	writes	

1. Typical data retention values are based on intrinsic capability of the technology measured at high temperature derated to 25°C. For additional information on how Freescale defines typical data retention, please refer to Engineering Bulletin EB618.
2. Data retention is based on  $T_{javg} = 55^{\circ}\text{C}$  (temperature profile over the lifetime of the application).
3. Cycling endurance represents number of program/erase cycles at  $-40^{\circ}\text{C} \leq T_j \leq 125^{\circ}\text{C}$ .
4. Write endurance represents the number of writes to each FlexRAM location at  $-40^{\circ}\text{C} \leq T_j \leq 125^{\circ}\text{C}$  influenced by the cycling endurance of the FlexNVM (same value as data flash) and the allocated EEPROM backup per subsystem. Minimum value assumes all byte-writes to FlexRAM.

#### 6.4.1.5 Write endurance to FlexRAM for EEPROM

When the FlexNVM partition code is not set to full data flash, the EEPROM data set size can be set to any of several non-zero values.

The bytes not assigned to data flash via the FlexNVM partition code are used by the FTFL to obtain an effective endurance increase for the EEPROM data. The built-in EEPROM record management system raises the number of program/erase cycles that can be attained prior to device wear-out by cycling the EEPROM data through a larger EEPROM NVM storage space.

While different partitions of the FlexNVM are available, the intention is that a single choice for the FlexNVM partition code and EEPROM data set size is used throughout the entire lifetime of a given application. The EEPROM endurance equation and graph shown below assume that only one configuration is ever used.

$$\text{Writes}_{\text{subsystem}} = \frac{\text{EEPROM} - 2 \times \text{EESPLIT} \times \text{EESIZE}}{\text{EESPLIT} \times \text{EESIZE}} \times \text{Write}_{\text{efficiency}} \times n_{nvmcygd}$$

where

- Writes\_subsystem — minimum number of writes to each FlexRAM location for subsystem (each subsystem can have different endurance)
- EEPROM — allocated FlexNVM for each EEPROM subsystem based on DEPART; entered with Program Partition command
- EEESPLIT — FlexRAM split factor for subsystem; entered with the Program Partition command
- EEESIZE — allocated FlexRAM based on DEPART; entered with Program Partition command
- Write\_efficiency —
  - 0.25 for 8-bit writes to FlexRAM
  - 0.50 for 16-bit or 32-bit writes to FlexRAM
- $n_{\text{nvmcycd}}$  — data flash cycling endurance

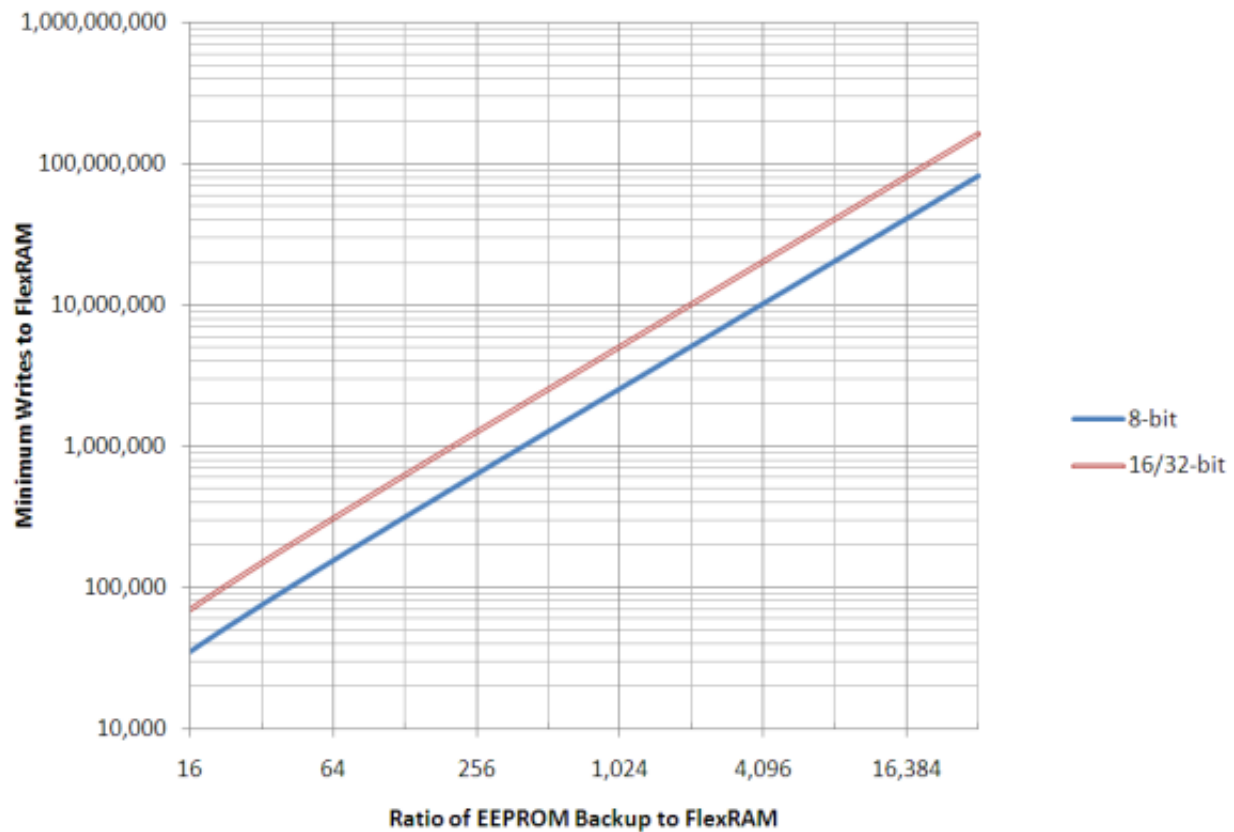


Figure 9. EEPROM backup writes to FlexRAM

## 6.4.2 EzPort Switching Specifications

Table 22. EzPort switching specifications

Num	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
EP1	EZP_CK frequency of operation (all commands except READ)	—	$f_{SYS}/2$	MHz
EP1a	EZP_CK frequency of operation (READ command)	—	$f_{SYS}/8$	MHz
EP2	$\overline{EZP\_CS}$ negation to next $\overline{EZP\_CS}$ assertion	$2 \times t_{EZP\_CK}$	—	ns
EP3	$\overline{EZP\_CS}$ input valid to EZP_CK high (setup)	5	—	ns
EP4	EZP_CK high to $\overline{EZP\_CS}$ input invalid (hold)	5	—	ns
EP5	EZP_D input valid to EZP_CK high (setup)	2	—	ns
EP6	EZP_CK high to EZP_D input invalid (hold)	5	—	ns
EP7	EZP_CK low to EZP_Q output valid (setup)	—	12	ns
EP8	EZP_CK low to EZP_Q output invalid (hold)	0	—	ns
EP9	$\overline{EZP\_CS}$ negation to EZP_Q tri-state	—	12	ns

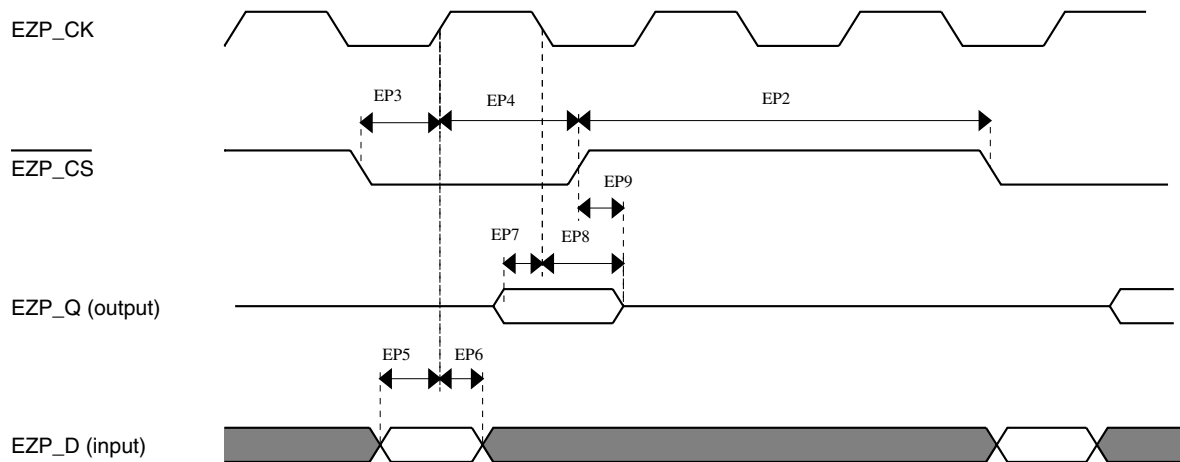


Figure 10. EzPort Timing Diagram

## 6.4.3 Flexbus Switching Specifications

All processor bus timings are synchronous; input setup/hold and output delay are given in respect to the rising edge of a reference clock, FB\_CLK. The FB\_CLK frequency may be the same as the internal system bus frequency or an integer divider of that frequency.

The following timing numbers indicate when data is latched or driven onto the external bus, relative to the Flexbus output clock (FB\_CLK). All other timing relationships can be derived from these values.

**Table 23. Flexbus switching specifications**

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	2.7	3.6	V	
	Frequency of operation	—	50	Mhz	
FB1	Clock period	20	—	ns	
FB2	Address, data, and control output valid	TBD	11.5	ns	1
FB3	Address, data, and control output hold	0	—	ns	1
FB4	Data and $\overline{\text{FB\_TA}}$ input setup	8.5	—	ns	2
FB5	Data and $\overline{\text{FB\_TA}}$ input hold	0.5	—	ns	2

1. Specification is valid for all FB\_AD[31:0], FB\_BE/BWE $\overline{n}$ , FB\_CS $\overline{n}$ , FB\_OE, FB\_R/W, FB\_TBST, FB\_TSIZE[1:0], FB\_ALE, and FB\_TS.
2. Specification is valid for all FB\_AD[31:0] and  $\overline{\text{FB\_TA}}$ .



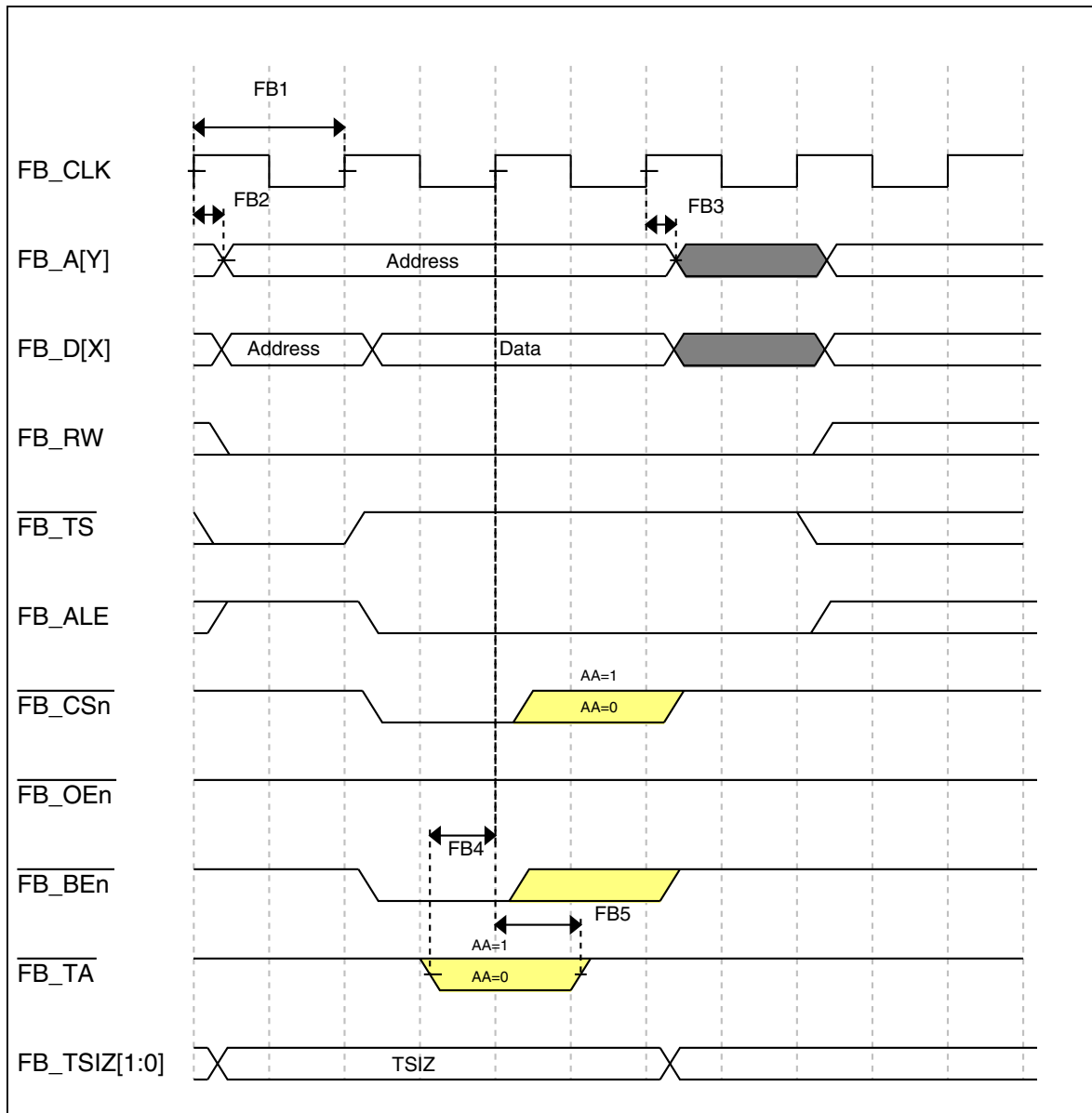


Figure 12. FlexBus write timing diagram

## 6.5 Security and integrity modules

There are no specifications necessary for the device's security and integrity modules.

## 6.6 Analog

## 6.6.1 ADC electrical specifications

The 16-bit accuracy specifications listed in [Table 24](#) and [Table 25](#) are achievable on the differential pins ADCx\_DP0, ADCx\_DM0, ADCx\_DP1, ADCx\_DM1, ADCx\_DP3, and ADCx\_DP3.

The ADCx\_DP2 and ADCx\_DM2 ADC inputs are used as the PGA inputs and are not direct device pins. Accuracy specifications for these pins are defined in [Table 26](#) and [Table 27](#).

All other ADC channels meet the 13-bit differential/12-bit single-ended accuracy specifications.

### 6.6.1.1 16-bit ADC operating conditions

**Table 24. 16-bit ADC operating conditions**

Symbol	Description	Conditions	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
V <sub>DDA</sub>	Supply voltage	Absolute	1.71	—	3.6	V	
ΔV <sub>DDA</sub>	Supply voltage	Delta to V <sub>DD</sub> (V <sub>DD</sub> -V <sub>DDA</sub> )	-100	0	+100	mV	<a href="#">2</a>
ΔV <sub>SSA</sub>	Ground voltage	Delta to V <sub>SS</sub> (V <sub>SS</sub> -V <sub>SSA</sub> )	-100	0	+100	mV	<a href="#">2</a>
V <sub>REFH</sub>	ADC reference voltage high		1.13	V <sub>DDA</sub>	V <sub>DDA</sub>	V	
V <sub>REFL</sub>	Reference voltage low		V <sub>SSA</sub>	V <sub>SSA</sub>	V <sub>SSA</sub>	V	
V <sub>ADIN</sub>	Input voltage		V <sub>REFL</sub>	—	V <sub>REFH</sub>	V	
C <sub>ADIN</sub>	Input capacitance	<ul style="list-style-type: none"> <li>• 16 bit modes</li> <li>• 8/10/12 bit modes</li> </ul>	—	8	10	pF	
R <sub>ADIN</sub>	Input resistance		—	2	5	kΩ	
R <sub>AS</sub>	Analog source resistance	13/12 bit modes f <sub>ADCK</sub> < 4MHz	—	—	5	kΩ	<a href="#">3</a>
f <sub>ADCK</sub>	ADC conversion clock frequency	≤13 bit modes	1.0	—	18.0	MHz	<a href="#">4</a>
f <sub>ADCK</sub>	ADC conversion clock frequency	16 bit modes	2.0	—	12.0	MHz	<a href="#">5</a>

Table continues on the next page...



**Table 24. 16-bit ADC operating conditions (continued)**

Symbol	Description	Conditions	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
$C_{rate}$	ADC conversion rate	$\leq 13$ bit modes No ADC hardware averaging Continuous conversions enabled Peripheral clock = 50MHz	18.484	—	818.330	Ksps	6
$C_{rate}$	ADC conversion rate	16 bit modes No ADC hardware averaging Continuous conversions enabled Peripheral clock = 50MHz	37.037	—	361.402	Ksps	7

1. Typical values assume  $V_{DDA} = 3.0$  V, Temp = 25°C,  $f_{ADCK} = 1.0$  MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
2. DC potential difference.
3. This resistance is external to MCU. The analog source resistance should be kept as low as possible in order to achieve the best results. The results in this datasheet were derived from a system which has  $<8 \Omega$  analog source resistance. The  $R_{AS}/C_{AS}$  time constant should be kept to  $<1$  ns.
4. In order to use the maximum ADC conversion clock frequency ADHSC bit should be set and the ADLPC should be clear.
5. In order to use the maximum ADC conversion clock frequency ADHSC bit should be set and the ADLPC should be clear.
6. For guidelines and examples of conversion rate calculation please download the ADC calculator tool [http://cache.freescale.com/files/soft\\_dev\\_tools/software/app\\_software/converters/ADC\\_CALCULATOR\\_CNV.zip?fp=1](http://cache.freescale.com/files/soft_dev_tools/software/app_software/converters/ADC_CALCULATOR_CNV.zip?fp=1)
7. For guidelines and examples of conversion rate calculation please download the ADC calculator tool [http://cache.freescale.com/files/soft\\_dev\\_tools/software/app\\_software/converters/ADC\\_CALCULATOR\\_CNV.zip?fp=1](http://cache.freescale.com/files/soft_dev_tools/software/app_software/converters/ADC_CALCULATOR_CNV.zip?fp=1)

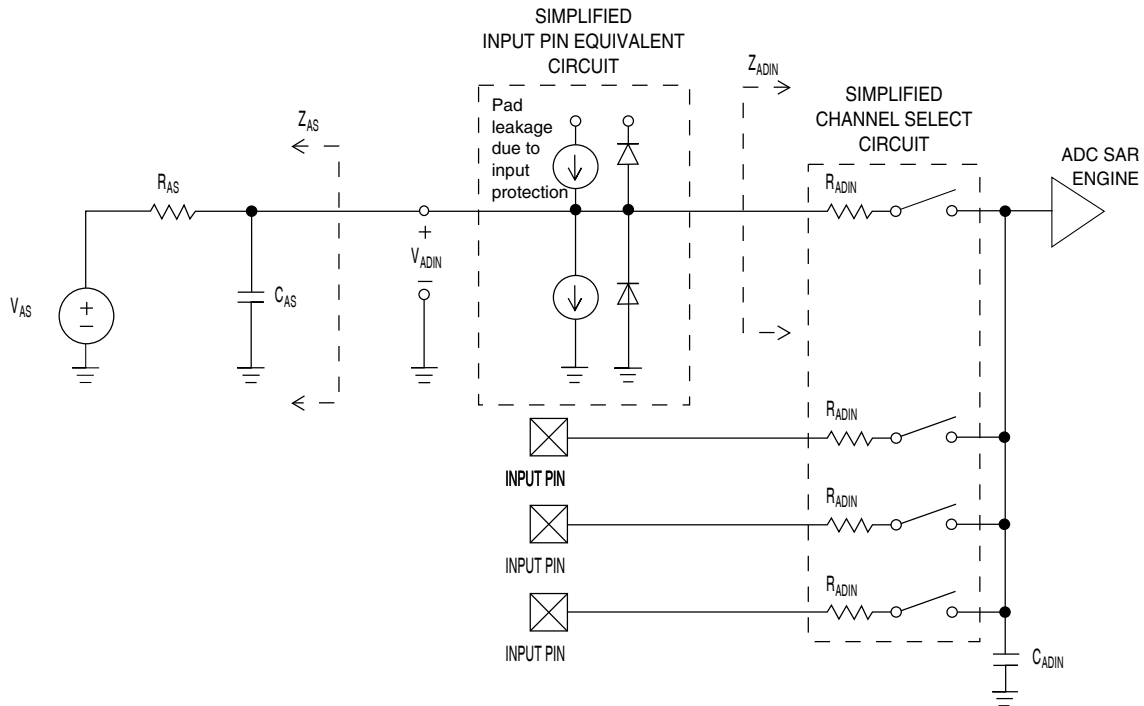


Figure 13. ADC input impedance equivalency diagram

6.6.1.2 16-bit ADC electrical characteristics

Table 25. 16-bit ADC characteristics ( $V_{REFH} = V_{DDA}$ ,  $V_{REFL} = V_{SSA}$ )

Symbol	Description	Conditions <sup>1</sup>	Min.	Typ. <sup>2</sup>	Max.	Unit	Notes
$I_{DDA}$	Supply current		0.215	—	1.7	mA	3
$f_{ADACK}$	ADC asynchronous clock source	<ul style="list-style-type: none"> <li>ADLPC=1, ADHSC=0</li> <li>ADLPC=1, ADHSC=1</li> <li>ADLPC=0, ADHSC=0</li> <li>ADLPC=0, ADHSC=1</li> </ul>	—	2.4	—	MHz	$t_{ADACK} = 1/f_{ADACK}$
			—	4.0	—	MHz	
			—	5.2	—	MHz	
			—	6.2	—	MHz	
	Sample Time	See Reference Manual chapter for sample times					
	Conversion Time	The ADC calculator tool can be used to determine ADC conversion times for different ADC configurations: <a href="http://cache.freescale.com/files/soft_dev_tools/software/app_software/converters/ADC_CALCULATOR_CNV.zip?fp=1">http://cache.freescale.com/files/soft_dev_tools/software/app_software/converters/ADC_CALCULATOR_CNV.zip?fp=1</a>					
TUE	Total unadjusted error	<ul style="list-style-type: none"> <li>≤13 bit modes</li> <li>&lt;12 bit modes</li> </ul>		±0.8	±TBD	LSB <sup>4</sup>	ADC conversion clock <12MHz, Max hardware averaging (AVGE = %1, AVGS = %11)

Table continues on the next page...

**Table 25. 16-bit ADC characteristics ( $V_{REFH} = V_{DDA}$ ,  $V_{REFL} = V_{SSA}$ ) (continued)**

Symbol	Description	Conditions <sup>1</sup>	Min.	Typ. <sup>2</sup>	Max.	Unit	Notes
DNL	Differential non-linearity	<ul style="list-style-type: none"> <li>• <math>\leq 13</math> bit modes</li> <li>• <math>&lt; 12</math> bit modes</li> </ul>		$\pm 0.7$ $\pm 0.2$	$\pm \text{TBD}$ $\pm 0.5$	LSB <sup>4</sup>	ADC conversion clock $< 12\text{MHz}$ , Max hardware averaging (AVGE = %1, AVGS = %11)
INL	Integral non-linearity	<ul style="list-style-type: none"> <li>• <math>\leq 13</math> bit modes</li> <li>• <math>&lt; 12</math> bit modes</li> </ul>	—	$\pm 1.0$ $\pm 0.5$	$\pm \text{TBD}$ $\pm \text{TBD}$	LSB <sup>4</sup>	Max averaging
$E_{FS}$	Full-scale error	<ul style="list-style-type: none"> <li>• <math>\leq 13</math> bit modes</li> <li>• <math>&lt; 12</math> bit modes</li> </ul>	—	$\pm 0.4$ $\pm 1.0$	$\pm \text{TBD}$ $\pm \text{TBD}$	LSB <sup>4</sup>	$V_{ADIN} = V_{DDA}$
$E_Q$	Quantization error	<ul style="list-style-type: none"> <li>• 16 bit modes</li> <li>• <math>\leq 13</math> bit modes</li> </ul>	—	$-1$ to $0$ —	— $\pm 0.5$	LSB <sup>4</sup>	
ENOB	Effective number of bits	16 bit differential mode					5
		<ul style="list-style-type: none"> <li>• Avg=32</li> <li>• Avg=1</li> </ul>	TBD	13.6	TBD	bits	
			TBD	13.2	TBD	bits	
		16 bit single-ended mode					
	<ul style="list-style-type: none"> <li>• Avg=32</li> <li>• Avg=1</li> </ul>	TBD	TBD	TBD	bits		
		TBD	TBD	TBD	bits		
SINAD	Signal-to-noise plus distortion	See ENOB	6.02 × ENOB + 1.76			dB	
THD	Total harmonic distortion	16 bit differential mode					5
		<ul style="list-style-type: none"> <li>• Avg=32</li> </ul>	—	-94	TBD	dB	
		16 bit single-ended mode					
		<ul style="list-style-type: none"> <li>• Avg=32</li> </ul>	—	TBD	TBD	dB	
SFDR	Spurious free dynamic range	16 bit differential mode					5
		<ul style="list-style-type: none"> <li>• Avg=32</li> </ul>	TBD	95	—	dB	
		16 bit single-ended mode					
		<ul style="list-style-type: none"> <li>• Avg=32</li> </ul>	TBD	TBD	—	dB	

Table continues on the next page...

**Table 25. 16-bit ADC characteristics ( $V_{REFH} = V_{DDA}$ ,  $V_{REFL} = V_{SSA}$ ) (continued)**

Symbol	Description	Conditions <sup>1</sup>	Min.	Typ. <sup>2</sup>	Max.	Unit	Notes
$E_{IL}$	Input leakage error		$I_{in} \times R_{AS}$			mV	$I_{in}$ = leakage current  (refer to the MCU's voltage and current operating ratings)
	Temp sensor slope	<ul style="list-style-type: none"> <li>• <math>-40^{\circ}\text{C}</math> to <math>25^{\circ}\text{C}</math></li> <li>• <math>25^{\circ}\text{C}</math> to <math>105^{\circ}\text{C}</math></li> </ul>	—	TBD	—	mV/ $^{\circ}\text{C}$	
			—	TBD	—	mV/ $^{\circ}\text{C}$	
$V_{TEMP25}$	Temp sensor voltage	$25^{\circ}\text{C}$	—	TBD	—	mV	

1. All accuracy numbers assume the ADC is calibrated with  $V_{REFH} = V_{DDA}$
2. Typical values assume  $V_{DDA} = 3.0\text{ V}$ , Temp =  $25^{\circ}\text{C}$ ,  $f_{ADCK} = 2.0\text{ MHz}$  unless otherwise stated. Typical values are for reference only and are not tested in production.
3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and the ADLPC bit (low power). For lowest power operation the ADLPC bit should be set, the HSC bit should be clear with 1MHz ADC conversion clock speed.
4.  $1\text{ LSB} = (V_{REFH} - V_{REFL})/2^N$
5. Input data is 1 kHz sine wave.

FIGURE TBD

**Figure 14. Typical TUE vs. ADC conversion rate 12-bit single-ended mode**

FIGURE TBD

**Figure 15. Typical ENOB vs. Averaging for 16-bit differential and 16-bit single-ended modes**

### 6.6.1.3 16-bit ADC with PGA operating conditions

**Table 26. 16-bit ADC with PGA operating conditions**

Symbol	Description	Conditions	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
$V_{DDA}$	Supply voltage	Absolute	1.71	—	3.6	V	
$V_{REFPGA}$	PGA ref voltage		$V_{REFOUT}$	$V_{REFOUT}$	$V_{REFOUT}$	V	2, 3
$V_{ADIN}$	Input voltage		$V_{SSA}$	—	$V_{DDA}$	V	
$V_{CM}$	Input Common Mode range		$V_{SSA}$	—	$V_{DDA}$	V	

Table continues on the next page...

**Table 26. 16-bit ADC with PGA operating conditions (continued)**

Symbol	Description	Conditions	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
R <sub>PGAD</sub>	Differential input impedance	Gain = 1, 2, 4, 8 Gain = 16, 32 Gain = 64	—	128 64 32	—	kΩ	IN+ to IN- <sup>4</sup>
R <sub>AS</sub>	Analog source resistance		—	100	—	Ω	5
T <sub>S</sub>	ADC sampling time		1.25	—	—	μs	6

1. Typical values assume V<sub>DDA</sub> = 3.0 V, Temp = 25°C, f<sub>ADCK</sub> = 6 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
2. ADC must be configured to use the internal voltage reference (VREFOUT)
3. PGA reference connected to the VREFOUT pin. If the user wishes to drive VREFOUT with a voltage other than the output of the VREF module, the VREF module must be disabled.
4. For single ended configurations the input impedance of the driven input is 1/2.
5. The analog source resistance (R<sub>AS</sub>), external to MCU, should be kept as minimum as possible. Increased R<sub>AS</sub> causes drop in PGA gain without affecting other performances. This is not dependent on ADC clock frequency.
6. The minimum sampling time is dependent on input signal frequency and ADC mode of operation. A minimum of 1.25μs time should be allowed for F<sub>in</sub>=4 kHz at 16-bit differential mode. Recommended ADC setting is: ADLSMP=1, ADLSTS=2 at 8 MHz ADC clock.

#### 6.6.1.4 16-bit ADC with PGA characteristics

**Table 27. 16-bit ADC with PGA characteristics**

Symbol	Description	Conditions	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
I <sub>DDA_PGA</sub>	Supply current		—	590	TBD	μA	
I <sub>DC_PGA</sub>	Input DC current		$\frac{2}{R_{PGAD}} \left( \frac{V_{REFPGA} \times 0.583 - V_{CM}}{(Gain+1)} \right)$			A	2
I <sub>ILKG</sub>	Input Leakage current	PGA disabled	—	TBD	TBD	μA	3
G	Gain <sup>4</sup>	<ul style="list-style-type: none"> <li>• PGAG=0</li> <li>• PGAG=1</li> <li>• PGAG=2</li> <li>• PGAG=3</li> <li>• PGAG=4</li> <li>• PGAG=5</li> <li>• PGAG=6</li> </ul>	TBD	0.98	TBD		R <sub>AS</sub> < 100Ω
BW	Input signal bandwidth	• 16-bit modes	—	—	4	kHz	
		• < 16-bit modes	—	—	40	kHz	
PSRR	Power supply rejection ration	Gain=1	TBD	TBD	—	dB	V <sub>DDA</sub> = 3V ±100mV, f <sub>VDDA</sub> = 50Hz, 60Hz

Table continues on the next page...

**Table 27. 16-bit ADC with PGA characteristics (continued)**

Symbol	Description	Conditions	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
CMRR	Common mode rejection ratio	<ul style="list-style-type: none"> <li>Gain=1</li> <li>Gain=64</li> </ul>	TBD	TBD	—	dB	$V_{CM}=500mV_{pp}$ , $f_{VCM}=50Hz$ , $100Hz$
			TBD	TBD	—	dB	
$V_{OFS}$	Input offset voltage		—	0.2	TBD	mV	Gain=1, ADC Averaging=32
$T_{GSW}$	Gain switching settling time		—	—	10	μs	5
dG/dT	Gain drift over temperature	<ul style="list-style-type: none"> <li>Gain=1</li> <li>Gain=64</li> </ul>	—	TBD	TBD	ppm/°C	0 to 50°C
			—	TBD	TBD	ppm/°C	
$dV_{OFS}/dT$	Offset drift over temperature	Gain=1	—	TBD	TBD	ppm/°C	0 to 50°C, ADC Averaging=32
dG/dV <sub>DDA</sub>	Gain drift over supply voltage	<ul style="list-style-type: none"> <li>Gain=1</li> <li>Gain=64</li> </ul>	—	TBD	TBD	%/V	V <sub>DDA</sub> from 1.71 to 3.6V
			—	TBD	TBD	%/V	
$E_{IL}$	Input leakage error	All modes	$I_{in} \times R_{AS}$			mV	$I_{in}$ = leakage current (refer to the MCU's voltage and current operating ratings)
$V_{PP,DIFF}$	Maximum differential input signal swing		$\left( \frac{(\min(V_X, V_{DDA} - V_X) - 0.2) \times 4}{Gain} \right)$ where $V_X = V_{REFPGA} \times 0.583$			V	6
SNR	Signal-to-noise ratio	<ul style="list-style-type: none"> <li>Gain=1</li> <li>Gain=64</li> </ul>	TBD	83.0	—	dB	16-bit differential mode, Average=32
			TBD	57.5	—	dB	
THD	Total harmonic distortion	<ul style="list-style-type: none"> <li>Gain=1</li> <li>Gain=64</li> </ul>	TBD	89.4	—	dB	16-bit differential mode, Average=32, $f_{in}=500Hz$
			TBD	90.0	—	dB	
SFDR	Spurious free dynamic range	<ul style="list-style-type: none"> <li>Gain=1</li> <li>Gain=64</li> </ul>	TBD	90.9	—	dB	16-bit differential mode, Average=32, $f_{in}=500Hz$
			TBD	77.0	—	dB	

Table continues on the next page...

**Table 27. 16-bit ADC with PGA characteristics (continued)**

Symbol	Description	Conditions	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
ENOB	Effective number of bits	• Gain=1, Average=4	TBD	12.3	—	bits	16-bit differential mode, $f_{in}=500\text{Hz}$
		• Gain=1, Average=8	TBD	12.7	—	bits	
		• Gain=64, Average=4	TBD	8.4	—	bits	
		• Gain=64, Average=8	TBD	8.7	—	bits	
		• Gain=1, Average=32	TBD	13.3	—	bits	
		• Gain=2, Average=32	TBD	13.1	—	bits	
		• Gain=4, Average=32	TBD	12.5	—	bits	
		• Gain=8, Average=32	TBD	11.8	—	bits	
		• Gain=16, Average=32	TBD	11.1	—	bits	
		• Gain=32, Average=32	TBD	10.2	—	bits	
• Gain=64, Average=32	TBD	9.3	—	bits			
SINAD	Signal-to-noise plus distortion ratio	See ENOB	6.02 × ENOB + 1.76			dB	

1. Typical values assume  $V_{DDA}=3.0\text{V}$ ,  $\text{Temp}=25^{\circ}\text{C}$ ,  $f_{ADCK}=6\text{MHz}$  unless otherwise stated.
2. Between IN+ and IN-. The PGA draws a DC current from the input terminals. The magnitude of the DC current is a strong function of input common mode voltage ( $V_{CM}$ ) and the PGA gain.
3. This is the input leakage current of the module in addition to the PAD leakage current.
4.  $\text{Gain} = 2^{\text{PGA}}$
5. When the PGA gain is changed, it takes some time to settle the output for the ADC to work properly. During a gain switching, a few ADC outputs should be discarded (minimum two data samples, may be more depending on ADC sampling rate and time of the switching).
6. Limit the input signal swing so that the PGA does not saturate during operation. Input signal swing is dependent on the PGA reference voltage and gain setting.

## 6.6.2 CMP and 6-bit DAC electrical specifications

**Table 28. Comparator and 6-bit DAC electrical specifications**

Symbol	Description	Min.	Typ.	Max.	Unit
$V_{DD}$	Supply voltage	1.71	—	3.6	V
$I_{DDHS}$	Supply current, High-speed mode (EN=1, PMODE=1)	—	—	200	$\mu\text{A}$
$I_{DDL S}$	Supply current, low-speed mode (EN=1, PMODE=0)	—	—	20	$\mu\text{A}$
$V_{AIN}$	Analog input voltage	$V_{SS} - 0.3$	—	$V_{DD}$	V
$V_{AIO}$	Analog input offset voltage	—	—	20	mV

Table continues on the next page...

**Table 28. Comparator and 6-bit DAC electrical specifications (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit
$V_H$	Analog comparator hysteresis <sup>1</sup>				
	• CR0[HYSTCTR] = 00	—	5	—	mV
	• CR0[HYSTCTR] = 01	—	10	—	mV
	• CR0[HYSTCTR] = 10	—	20	—	mV
	• CR0[HYSTCTR] = 11	—	30	—	mV
$V_{CMPOH}$	Output high	$V_{DD} - 0.5$	—	—	V
$V_{CMPOI}$	Output low	—	—	0.5	V
$t_{DHS}$	Propagation delay, high-speed mode (EN=1, PMODE=1)	20	50	200	ns
$t_{DLS}$	Propagation delay, low-speed mode (EN=1, PMODE=0)	120	250	600	ns
	Analog comparator initialization delay <sup>2</sup>	—	—	TBD	ns
$I_{DAC6b}$	6-bit DAC current adder (enabled)	—	7	—	$\mu$ A
INL	6-bit DAC integral non-linearity	-0.5	—	0.5	LSB <sup>3</sup>
DNL	6-bit DAC differential non-linearity	-0.3	—	0.3	LSB

1. Typical hysteresis is measured with input voltage range limited to 0.6 to  $V_{DD}-0.6V$ .
2. Comparator initialization delay is defined as the time between software writes to change control inputs (Writes to DACEN, VRSEL, PSEL, MSEL, VOSEL) and the comparator output settling to a stable level.
3. 1 LSB =  $V_{reference}/64$



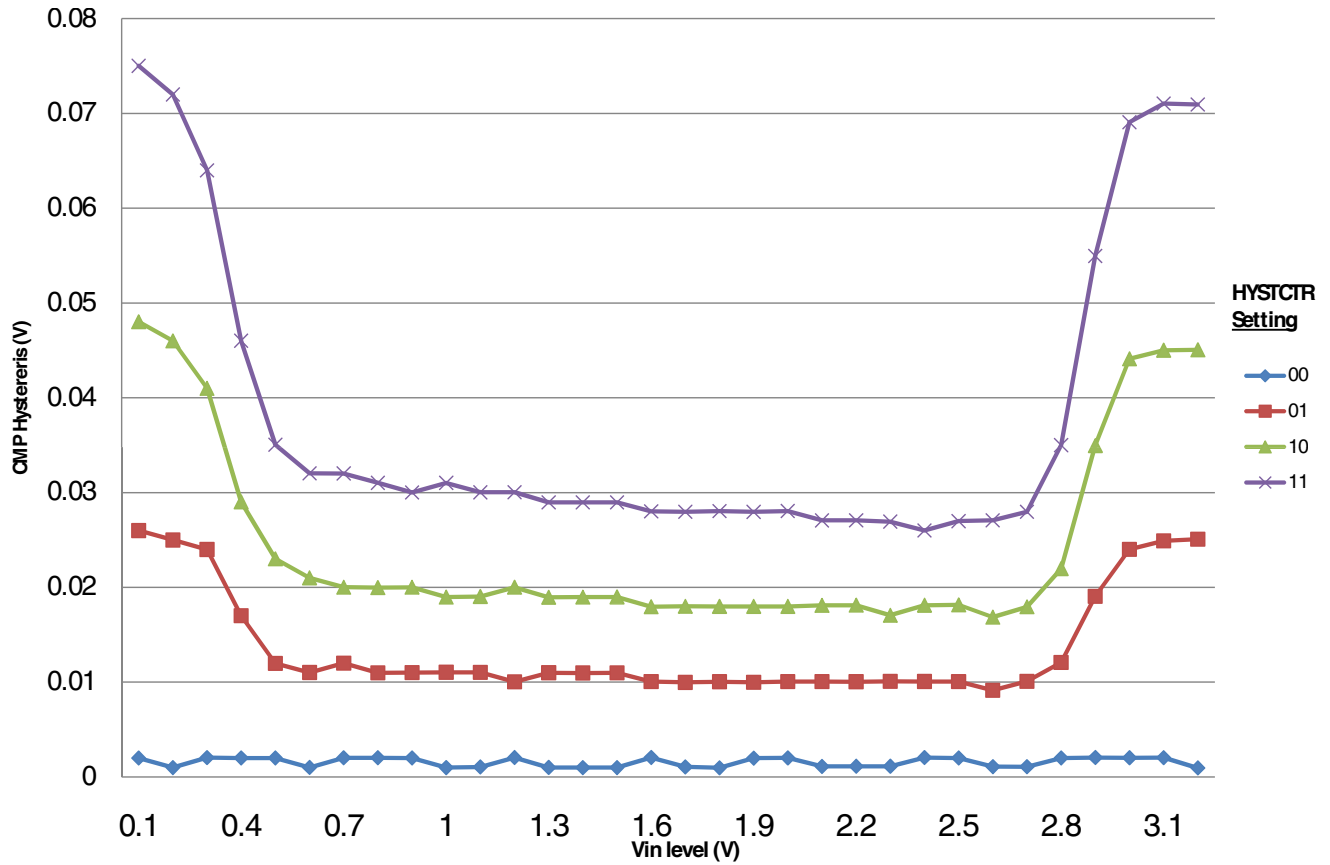


Figure 16. Typical hysteresis vs. Vin level (VDD=3.3V, PMODE=0)

## Peripheral operating requirements and behaviors

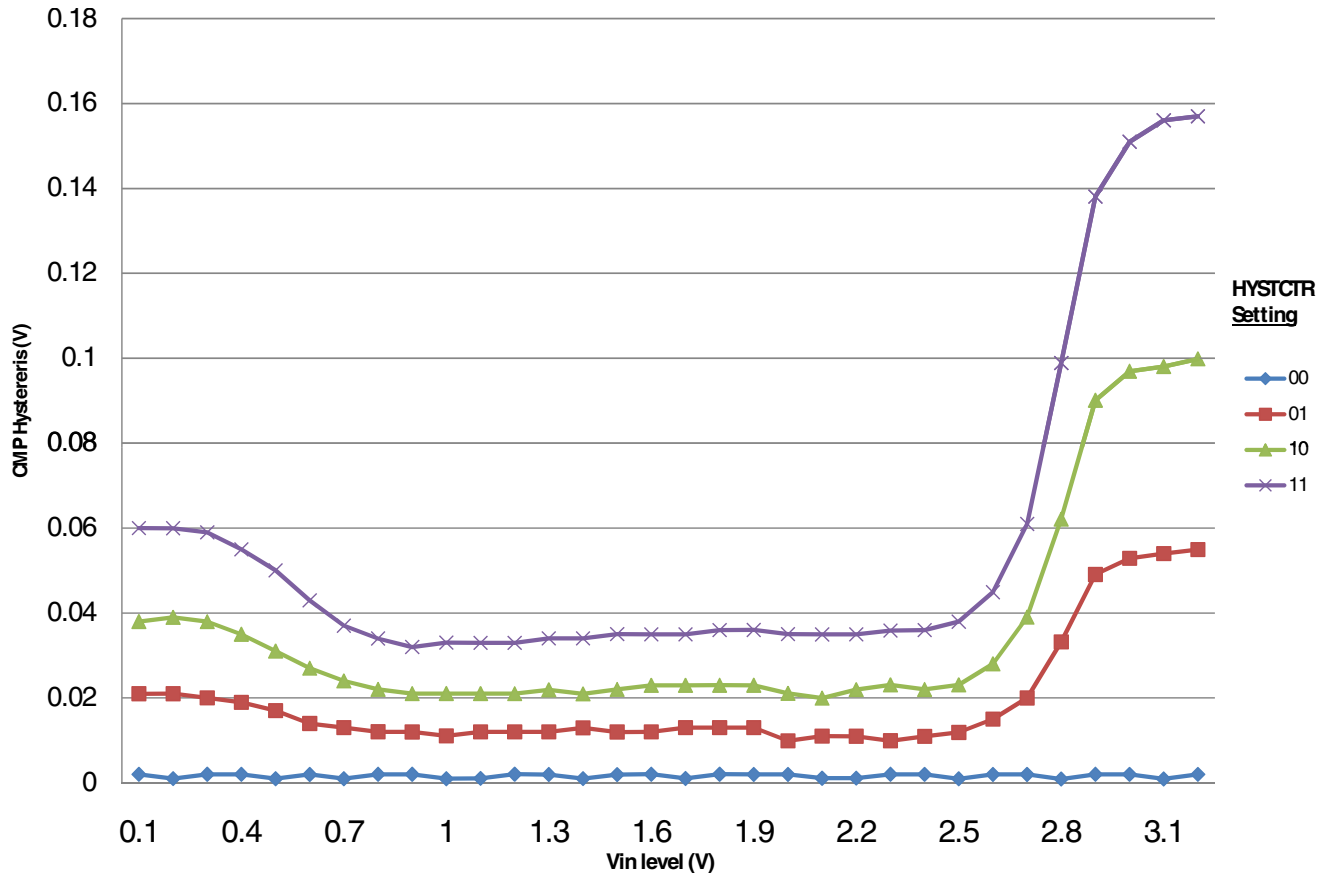


Figure 17. Typical hysteresis vs. Vin level (VDD=3.3V, PMODE=1)

## 6.6.3 12-bit DAC electrical characteristics

### 6.6.3.1 12-bit DAC operating requirements

Table 29. 12-bit DAC operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
$V_{DDA}$	Supply voltage	1.71	3.6	V	
$V_{DACR}$	Reference voltage	1.13	3.6	V	1
$T_A$	Temperature	-40	105	°C	
$C_L$	Output load capacitance	—	100	pF	2
$I_L$	Output load current	—	1	mA	

1. The DAC reference can be selected to be VDDA or the voltage output of the VREF module (VREFO)
2. A small load capacitance (47 pF) can improve the bandwidth performance of the DAC

### 6.6.3.2 12-bit DAC operating behaviors

Table 30. 12-bit DAC operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$I_{DDA\_DACLP}$	Supply current — low-power mode	—	—	150	$\mu\text{A}$	
$I_{DDA\_DACHP}$	Supply current — high-speed mode	—	—	700	$\mu\text{A}$	
$t_{DACLP}$	Full-scale settling time (0x080 to 0xF7F) — low-power mode	—	100	200	$\mu\text{s}$	1
$t_{DACHP}$	Full-scale settling time (0x080 to 0xF7F) — high-power mode	—	15	30	$\mu\text{s}$	1
$t_{CCDACLP}$	Code-to-code settling time (0xBF8 to 0xC08) — low-power mode	—	—	5	$\mu\text{s}$	1
$t_{CCDACHP}$	Code-to-code settling time (0xBF8 to 0xC08) — high-speed mode	1	TBD	—	$\mu\text{s}$	1
$V_{dacoutl}$	DAC output voltage range low — high-speed mode, no load, DAC set to 0x000	—	100	TBD	mV	
$V_{dacouth}$	DAC output voltage range high — high-speed mode, no load, DAC set to 0xFFFF	$V_{DACR} - 100$	—	$V_{DACR}$	mV	
INL	Integral non-linearity error — high speed mode	—	—	$\pm 8$	LSB	2
DNL	Differential non-linearity error — $V_{DACR} > 2\text{ V}$	—	—	$\pm 1$	LSB	3
DNL	Differential non-linearity error — $V_{DACR} = V_{REFO}$ (1.15 V)	—	—	$\pm 1$	LSB	4
$V_{OFFSET}$	Offset error	$\pm 0.4$	—	$\pm 0.8$	%FSR	5
$E_G$	Gain error	$\pm 0.1$	—	$\pm 0.6$	%FSR	5
PSRR	Power supply rejection ratio, $V_{DDA} > = 2.4\text{ V}$	60	—	90	dB	
$T_{CO}$	Temperature coefficient offset voltage	—	TBD	—	$\mu\text{V}/\text{C}$	
$T_{GE}$	Temperature coefficient gain error	—	TBD	—	ppm of FSR/C	
$A_C$	Offset aging coefficient	—	—	TBD	$\mu\text{V}/\text{yr}$	
$R_{op}$	Output resistance load = 3 k $\Omega$	—	—	250	$\Omega$	
SR	Slew rate -80h → F7Fh → 80h <ul style="list-style-type: none"> <li>High power (<math>SP_{HP}</math>)</li> <li>Low power (<math>SP_{LP}</math>)</li> </ul>	1.2 0.05	1.7 0.12	— —	$\text{V}/\mu\text{s}$	
CT	Channel to channel cross talk	—	—	-80	dB	
BW	3dB bandwidth <ul style="list-style-type: none"> <li>High power (<math>SP_{HP}</math>)</li> <li>Low power (<math>SP_{LP}</math>)</li> </ul>	550 40	— —	— —	kHz	

- Settling within  $\pm 1$  LSB
- The INL is measured for 0+100mV to  $V_{DACR} - 100\text{ mV}$
- The DNL is measured for 0+100 mV to  $V_{DACR} - 100\text{ mV}$
- The DNL is measured for 0+100mV to  $V_{DACR} - 100\text{ mV}$  with  $V_{DDA} > 2.4\text{V}$

Peripheral operating requirements and behaviors

5. Calculated by a best fit curve from  $V_{SS}+100$  mV to  $V_{REF}-100$  mV

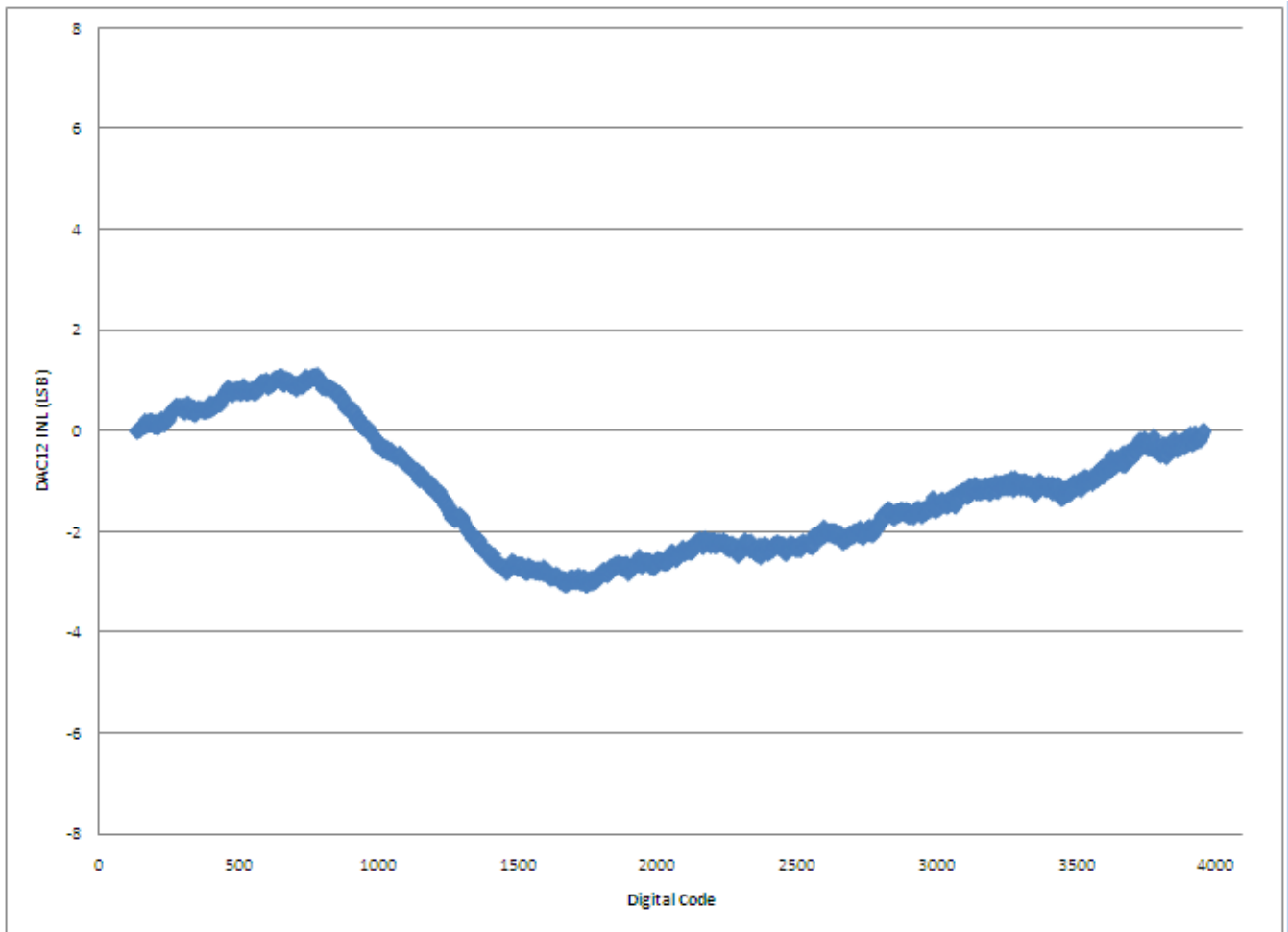


Figure 18. Typical INL error vs. digital code

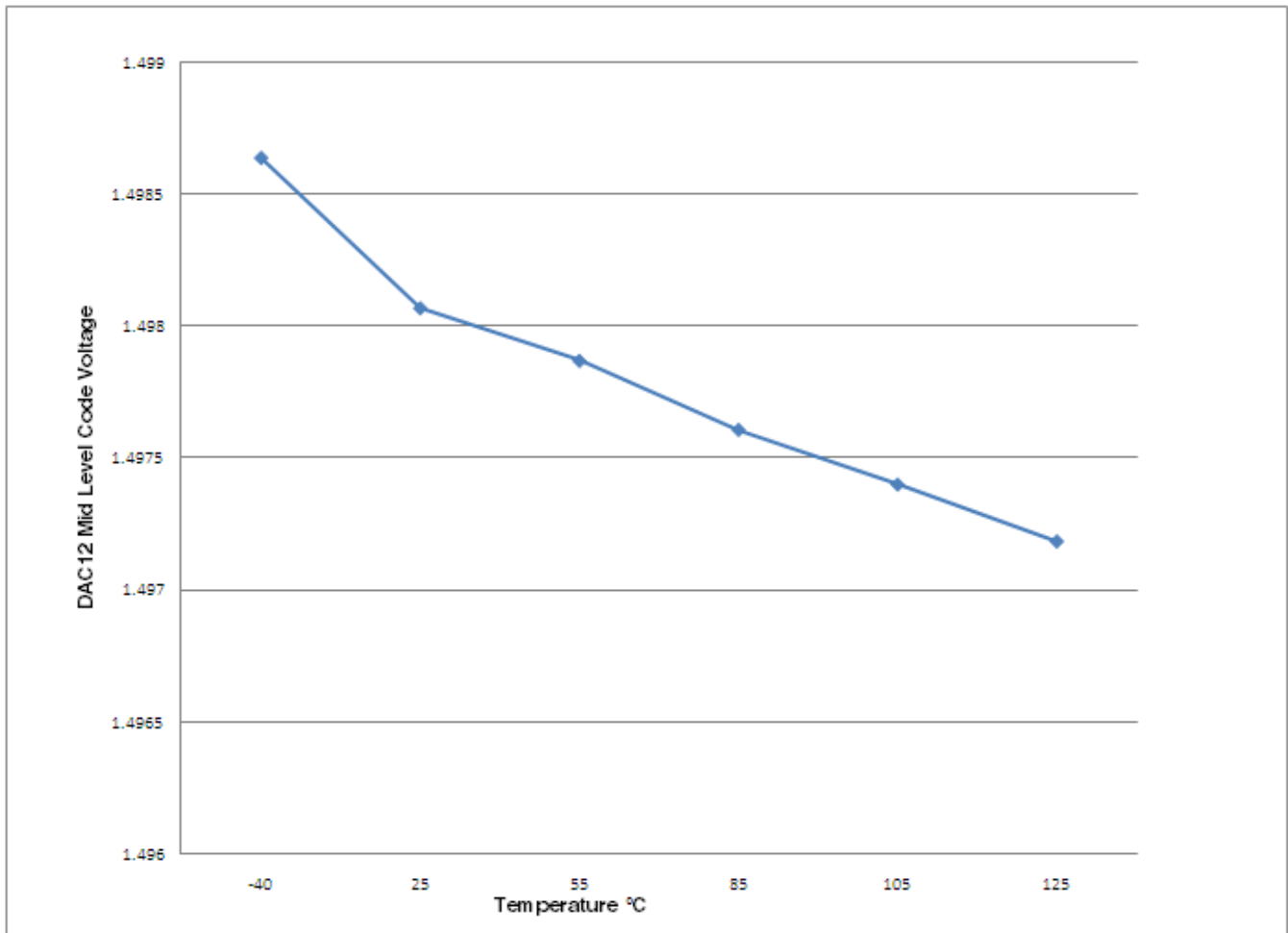


Figure 19. Offset at half scale vs. temperature

## 6.6.4 Voltage reference electrical specifications

Table 31. VREF full-range operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
$V_{DDA}$	Supply voltage	1.71	3.6	V	
$T_A$	Temperature	-40	105	°C	
$C_L$	Output load capacitance	—	100	nF	

Table 32. VREF full-range operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$V_{out}$	Voltage reference output with factory trim at nominal $V_{DDA}$ and temperature=25C	TBD	1.2	TBD	V	

Table continues on the next page...

**Table 32. VREF full-range operating behaviors (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$V_{out}$	Voltage reference output with factory trim	TBD	—	TBD	V	
$V_{out}$	Voltage reference output user trim	1.198	—	1.202	V	
$V_{step}$	Voltage reference trim step	—	0.5	—	mV	
$V_{drift}$	Temperature drift ( $V_{max} - V_{min}$ across the full temperature range)	—	—	20	mV	See <a href="#">Figure 20</a>
Ac	Aging coefficient	—	—	TBD	ppm/year	
$I_{bg}$	Bandgap only (MODE_LV = 00) current	—	—	TBD	$\mu$ A	
$I_{tr}$	Tight-regulation buffer (MODE_LV = 10) current	—	—	1.1	mA	
	Load regulation (MODE_LV = 10) current = $\pm 1.0$ mA	—	—	TBD	V	
$T_{stup}$	Buffer startup time	—	—	100	$\mu$ s	
DC	Line regulation (power supply rejection)	—	—	TBD	mV	
		-60	—	TBD	dB	

**Table 33. VREF limited-range operating requirements**

Symbol	Description	Min.	Max.	Unit	Notes
$T_A$	Temperature	0	50	$^{\circ}$ C	

**Table 34. VREF limited-range operating behaviors**

Symbol	Description	Min.	Max.	Unit	Notes
$V_{out}$	Voltage reference output with factory trim	TBD	TBD	V	

TBD

**Figure 20. Typical output vs. temperature**

TBD

**Figure 21. Typical output vs. VDD**

## 6.7 Timers

See [General switching specifications](#).

## 6.8 Communication interfaces

## 6.8.1 Ethernet switching specifications

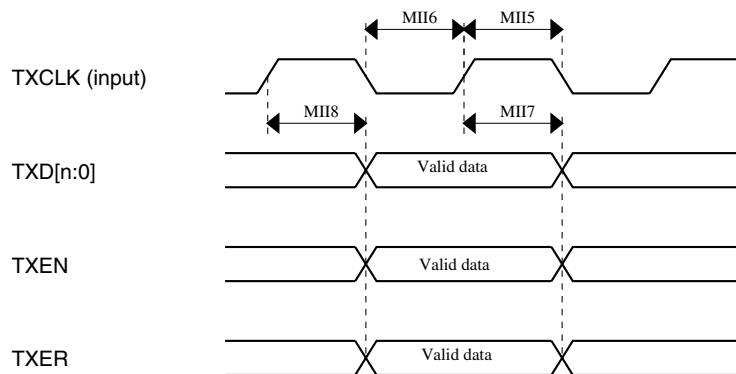
The following timing specs are defined at the chip I/O pin and must be translated appropriately to arrive at timing specs/constraints for the physical interface.

### 6.8.1.1 MII signal switching specifications

The following timing specs meet the requirements for MII style interfaces for a range of transceiver devices.

**Table 35. MII signal switching specifications**

Symbol	Description	Min.	Max.	Unit
—	RXCLK frequency	—	25	MHz
MII1	RXCLK pulse width high	35%	65%	RXCLK period
MII2	RXCLK pulse width low	35%	65%	RXCLK period
MII3	RXD[3:0], RXDV, RXER to RXCLK setup	5	—	ns
MII4	RXCLK to RXD[3:0], RXDV, RXER hold	5	—	ns
—	TXCLK frequency	—	25	MHz
MII5	TXCLK pulse width high	35%	65%	TXCLK period
MII6	TXCLK pulse width low	35%	65%	TXCLK period
MII7	TXCLK to TXD[3:0], TXEN, TXER invalid	2	—	ns
MII8	TXCLK to TXD[3:0], TXEN, TXER valid	—	25	ns



**Figure 22. MII transmit signal timing diagram**

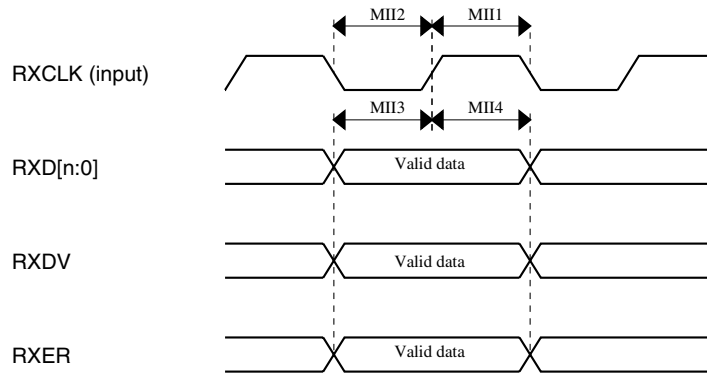


Figure 23. MII receive signal timing diagram

### 6.8.1.2 RMII signal switching specifications

The following timing specs meet the requirements for RMII style interfaces for a range of transceiver devices.

Table 36. RMII signal switching specifications

Num	Description	Min.	Max.	Unit
—	EXTAL frequency (RMII input clock RMII_CLK)	—	50	MHz
RMII1	RMII_CLK pulse width high	35%	65%	RMII_CLK period
RMII2	RMII_CLK pulse width low	35%	65%	RMII_CLK period
RMII3	RXD[1:0], CRS_DV, RXER to RMII_CLK setup	4	—	ns
RMII4	RMII_CLK to RXD[1:0], CRS_DV, RXER hold	2	—	ns
RMII7	RMII_CLK to TXD[1:0], TXEN invalid	4	—	ns
RMII8	RMII_CLK to TXD[1:0], TXEN valid	—	15	ns

### 6.8.2 USB electrical specifications

The USB electricals for the USB On-the-Go module conform to the standards documented by the Universal Serial Bus Implementers Forum. For the most up-to-date standards, visit <http://www.usb.org>.



### 6.8.3 USB DCD electrical specifications

Table 37. USB DCD electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
V <sub>DP_SRC</sub>	USB_DP source voltage (up to 250 $\mu$ A)	TBD	TBD	TBD	V
V <sub>LGC</sub>	Threshold voltage for logic high	0.8	—	2.0	V
I <sub>DP_SRC</sub>	USB_DP source current	7	10	13	$\mu$ A
I <sub>DM_SINK</sub>	USB_DM sink current	50	100	150	$\mu$ A
R <sub>DM_DWN</sub>	D- pulldown resistance for data pin contact detect	14.25	—	24.8	k $\Omega$
V <sub>DAT_REF</sub>	Data detect voltage	0.25	TBD	0.4	V

### 6.8.4 USB VREG electrical specifications

Table 38. USB VREG electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V <sub>REGIN</sub>	Input supply voltage	2.7	—	5.5	V	
I <sub>DDon</sub>	Quiescent current — Run mode, load current equal zero, input supply (V <sub>REGIN</sub> ) > 3.6 V	—	120	TBD	$\mu$ A	
I <sub>DDstby</sub>	Quiescent current — Standby mode, load current equal zero	—	1	TBD	$\mu$ A	
I <sub>DDoff</sub>	Quiescent current — Shutdown mode	—	500	—	nA	
		—	—	TBD	$\mu$ A	
I <sub>LOADrun</sub>	Maximum load current — Run mode	—	—	120	mA	
I <sub>LOADstby</sub>	Maximum load current — Standby mode	—	—	1	mA	
V <sub>Reg33out</sub>	Regulator output voltage — Input supply (V <sub>REGIN</sub> ) > 3.6 V	3	3.3	3.6	V	
		2.5	2.8	3.6	V	
V <sub>Reg33out</sub>	Regulator output voltage — Input supply (V <sub>REGIN</sub> ) < 3.6 V, pass-through mode	2.3	—	3.6	V	1
C <sub>OUT</sub>	External output capacitor	1.76	2.2	8.16	$\mu$ F	
ESR	External output capacitor equivalent series resistance	1	—	100	m $\Omega$	
I <sub>LIM</sub>	Current limitation threshold	185	290	395	mA	

1. Operating in pass-through mode: regulator output voltage equal to the input voltage minus a drop proportional to I<sub>Load</sub>.

## 6.8.5 CAN switching specifications

See [General switching specifications](#).

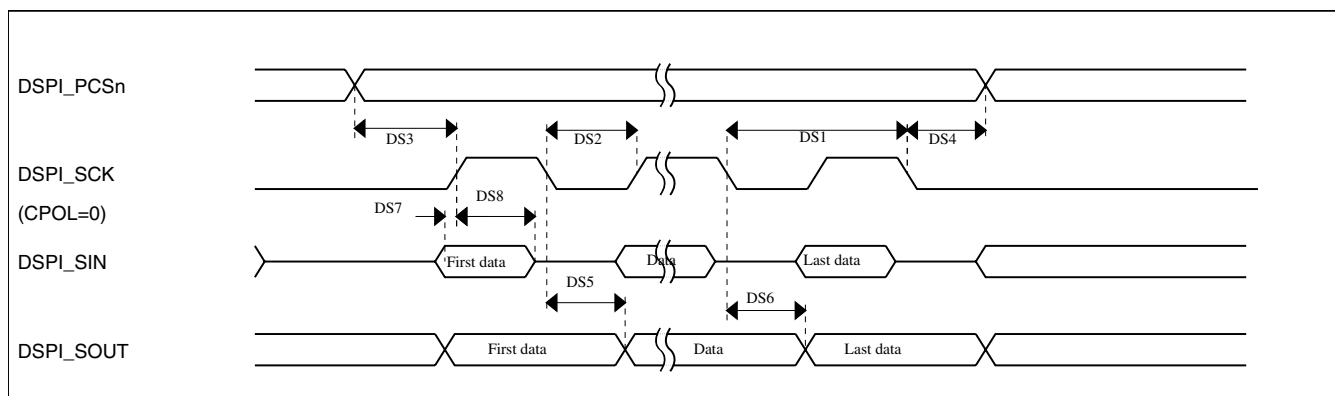
## 6.8.6 DSPI switching specifications (low-speed mode)

The DMA Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provides DSPI timing characteristics for classic SPI timing modes. Refer to the DSPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

**Table 39. Master mode DSPI timing (low-speed mode)**

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	1.71	3.6	V	1
	Frequency of operation	—	12.5	MHz	
DS1	DSPI_SCK output cycle time	$4 \times t_{\text{BCLK}}$	—	ns	
DS2	DSPI_SCK output high/low time	$(t_{\text{SCK}/2}) - 4$	$(t_{\text{SCK}/2}) + 4$	ns	
DS3	DSPI_PCS $n$ to DSPI_SCK output valid	$(t_{\text{SCK}/2}) - 4$	—	ns	
DS4	DSPI_SCK to DSPI_PCS $n$ output hold	$(t_{\text{SCK}/2}) - 4$	—	ns	
DS5	DSPI_SCK to DSPI_SOUT valid	—	10	ns	
DS6	DSPI_SCK to DSPI_SOUT invalid	-2	—	ns	
DS7	DSPI_SIN to DSPI_SCK input setup	15	—	ns	
DS8	DSPI_SCK to DSPI_SIN input hold	0	—	ns	

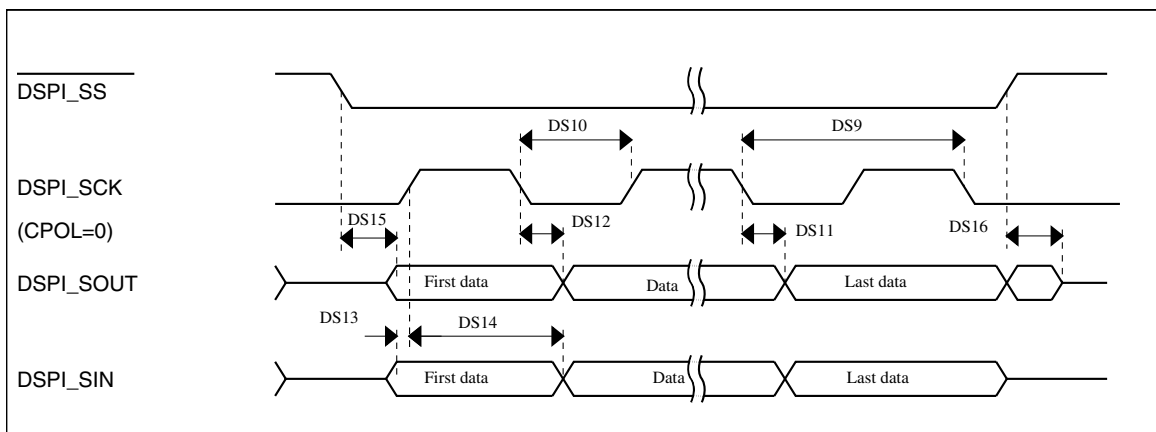
1. The DSPI module can operate across the entire operating voltage for the processor, but to run across the full voltage range the maximum frequency of operation is reduced.



**Figure 24. DSPI classic SPI timing — master mode**

**Table 40. Slave mode DSPI timing (low-speed mode)**

Num	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
	Frequency of operation	—	6.25	MHz
DS9	DSPI_SCK input cycle time	$8 \times t_{BCLK}$	—	ns
DS10	DSPI_SCK input high/low time	$(t_{SCK/2}) - 4$	$(t_{SCK/2}) + 4$	ns
DS11	DSPI_SCK to DSPI_SOUT valid	—	20	ns
DS12	DSPI_SCK to DSPI_SOUT invalid	0	—	ns
DS13	DSPI_SIN to DSPI_SCK input setup	5	—	ns
DS14	DSPI_SCK to DSPI_SIN input hold	15	—	ns
DS15	$\overline{\text{DSPI\_SS}}$ active to DSPI_SOUT driven	—	15	ns
DS16	$\overline{\text{DSPI\_SS}}$ inactive to DSPI_SOUT not driven	—	15	ns

**Figure 25. DSPI classic SPI timing — slave mode**

### 6.8.7 DSPI switching specifications (high-speed mode)

The DMA Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provide DSPI timing characteristics for classic SPI timing modes. Refer to the DSPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

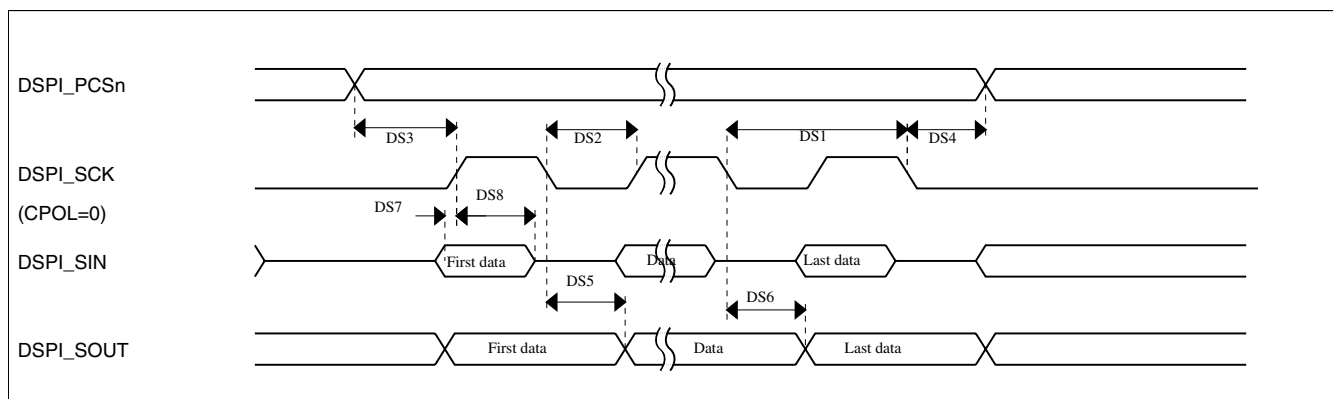
**Table 41. Master mode DSPI timing (high-speed mode)**

Num	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
	Frequency of operation	—	25	MHz

Table continues on the next page...

**Table 41. Master mode DSPI timing (high-speed mode) (continued)**

Num	Description	Min.	Max.	Unit
DS1	DSPI_SCK output cycle time	$2 \times t_{BCLK}$	—	ns
DS2	DSPI_SCK output high/low time	$(t_{SCK}/2) - 2$	$(t_{SCK}/2) + 2$	ns
DS3	DSPI_PCSn to DSPI_SCK output valid	$(t_{SCK}/2) - 2$	—	ns
DS4	DSPI_SCK to DSPI_PCSn output hold	$(t_{SCK}/2) - 2$	—	ns
DS5	DSPI_SCK to DSPI_SOUT valid	—	8.5	ns
DS6	DSPI_SCK to DSPI_SOUT invalid	-2	—	ns
DS7	DSPI_SIN to DSPI_SCK input setup	TBD	—	ns
DS8	DSPI_SCK to DSPI_SIN input hold	0	—	ns

**Figure 26. DSPI classic SPI timing — master mode****Table 42. Slave mode DSPI timing (high-speed mode)**

Num	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
	Frequency of operation		12.5	MHz
DS9	DSPI_SCK input cycle time	$4 \times t_{BCLK}$	—	ns
DS10	DSPI_SCK input high/low time	$(t_{SCK}/2) - 2$	$(t_{SCK}/2) + 2$	ns
DS11	DSPI_SCK to DSPI_SOUT valid	—	TBD	ns
DS12	DSPI_SCK to DSPI_SOUT invalid	0	—	ns
DS13	DSPI_SIN to DSPI_SCK input setup	2	—	ns
DS14	DSPI_SCK to DSPI_SIN input hold	7	—	ns
DS15	$\overline{DSPI\_SS}$ active to DSPI_SOUT driven	—	14	ns
DS16	$\overline{DSPI\_SS}$ inactive to DSPI_SOUT not driven	—	14	ns

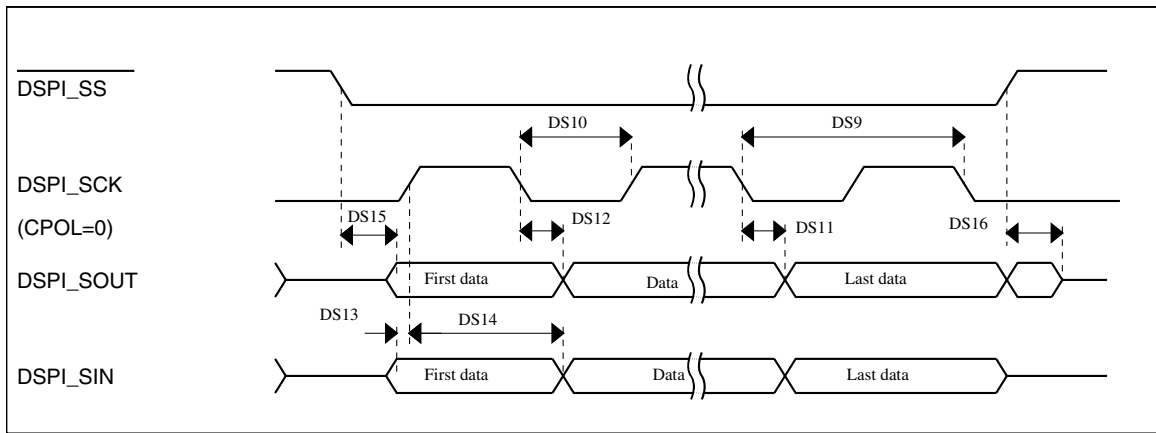


Figure 27. DSPI classic SPI timing — slave mode

### 6.8.8 I<sup>2</sup>C switching specifications

See [General switching specifications](#).

### 6.8.9 UART switching specifications

See [General switching specifications](#).

### 6.8.10 SDHC specifications

The following timing specs are defined at the chip I/O pin and must be translated appropriately to arrive at timing specs/constraints for the physical interface.

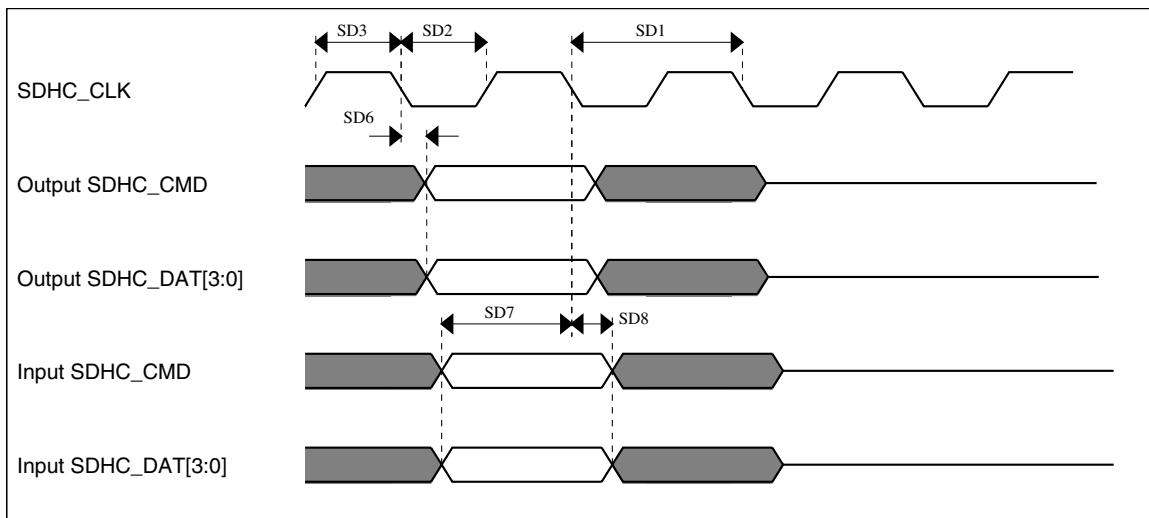
**Table 43. SDHC switching specifications**

Num	Symbol	Description	Min.	Max.	Unit
		Operating voltage	2.7	3.6	V
<b>Card input clock</b>					
SD1	f <sub>pp</sub>	Clock frequency (low speed)	0	400	kHz
	f <sub>pp</sub>	Clock frequency (SD\SDIO full speed)	0	25	MHz
	f <sub>pp</sub>	Clock frequency (MMC full speed)	0	20	MHz
	f <sub>OD</sub>	Clock frequency (identification mode)	0	400	kHz
SD2	t <sub>WL</sub>	Clock low time	7	—	ns
SD3	t <sub>WH</sub>	Clock high time	7	—	ns
SD4	t <sub>TLH</sub>	Clock rise time	—	3	ns

Table continues on the next page...

**Table 43. SDHC switching specifications  
(continued)**

Num	Symbol	Description	Min.	Max.	Unit
SD5	$t_{\text{THL}}$	Clock fall time	—	3	ns
<b>SDHC output / card inputs SDHC_CMD, SDHC_DAT (reference to SDHC_CLK)</b>					
SD6	$t_{\text{OD}}$	SDHC output delay (output valid)	-5	6.5	ns
<b>SDHC input / card inputs SDHC_CMD, SDHC_DAT (reference to SDHC_CLK)</b>					
SD7	$t_{\text{THL}}$	SDHC input setup time	5	—	ns
SD8	$t_{\text{THL}}$	SDHC input hold time	0	—	ns

**Figure 28. SDHC timing**

### 6.8.11 I<sup>2</sup>S switching specifications

This section provides the AC timings for the I<sup>2</sup>S in master (clocks driven) and slave modes (clocks input). All timings are given for non-inverted serial clock polarity (TCR[TSCPK] = 0, RCR[RSCKP] = 0) and a non-inverted frame sync (TCR[TFSI] = 0, RCR[RFSI] = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timings remain valid by inverting the clock signal (I2S\_BCLK) and/or the frame sync (I2S\_FS) shown in the figures below.

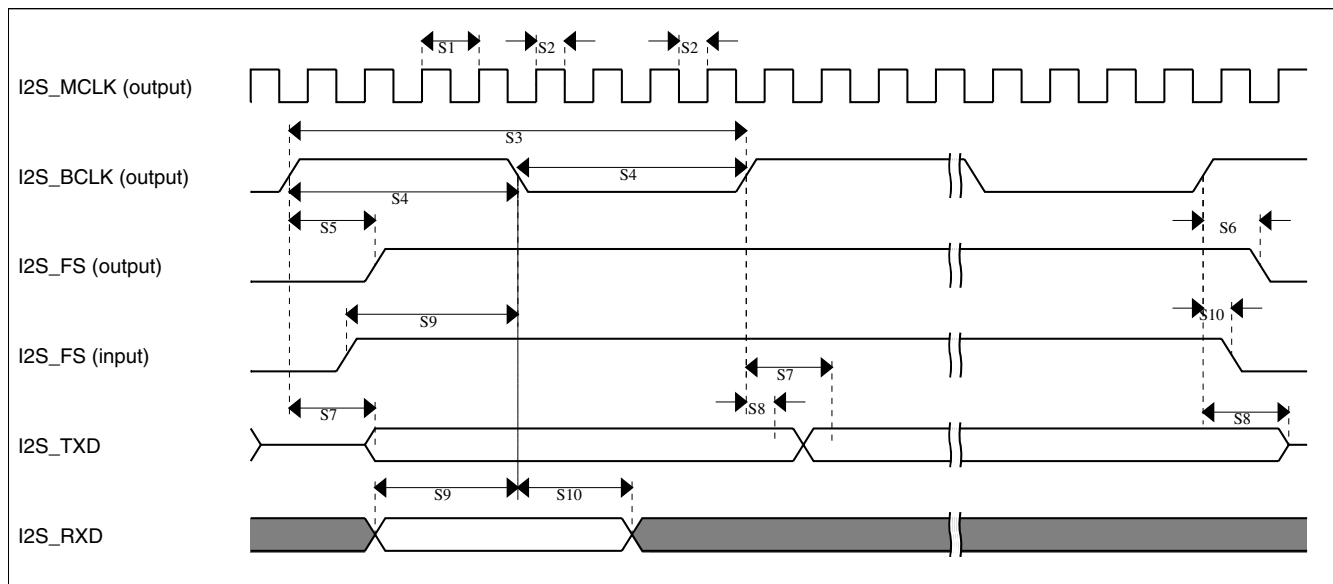
**Table 44. I<sup>2</sup>S master mode timing**

Num	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
S1	I2S_MCLK cycle time	$2 \times t_{\text{SYS}}$		ns

Table continues on the next page...

**Table 44. I<sup>2</sup>S master mode timing (continued)**

Num	Description	Min.	Max.	Unit
S2	I2S_MCLK pulse width high/low	45%	55%	MCLK period
S3	I2S_BCLK cycle time	5 x t <sub>sys</sub>	—	ns
S4	I2S_BCLK pulse width high/low	45%	55%	BCLK period
S5	I2S_BCLK to I2S_FS output valid	—	15	ns
S6	I2S_BCLK to I2S_FS output invalid	-2.5	—	ns
S7	I2S_BCLK to I2S_TXD valid	—	15	ns
S8	I2S_BCLK to I2S_TXD invalid	-3	—	ns
S9	I2S_RXD/I2S_FS input setup before I2S_BCLK	20	—	ns
S10	I2S_RXD/I2S_FS input hold after I2S_BCLK	0	—	ns

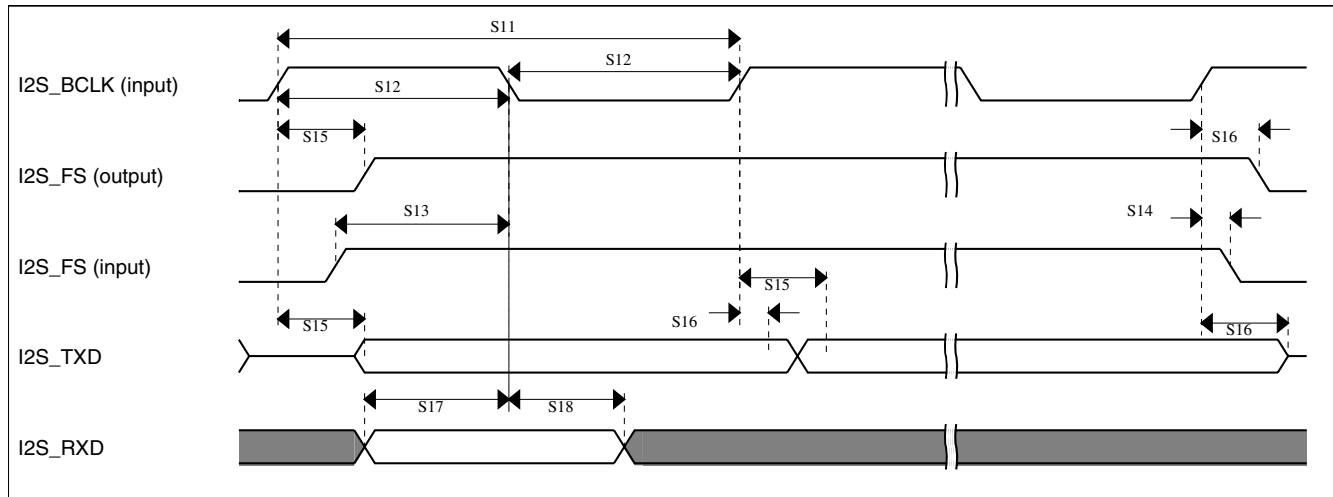
**Figure 29. I<sup>2</sup>S timing — master mode****Table 45. I<sup>2</sup>S slave mode timing**

Num	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
S11	I2S_BCLK cycle time (input)	8 x t <sub>sys</sub>	—	ns
S12	I2S_BCLK pulse width high/low (input)	45%	55%	MCLK period
S13	I2S_FS input setup before I2S_BCLK	10	—	ns
S14	I2S_FS input hold after I2S_BCLK	3	—	ns
S15	I2S_BCLK to I2S_TXD/I2S_FS output valid	—	20	ns
S16	I2S_BCLK to I2S_TXD/I2S_FS output invalid	0	—	ns
S17	I2S_RXD setup before I2S_BCLK	10	—	ns

Table continues on the next page...

Table 45. I<sup>2</sup>S slave mode timing (continued)

Num	Description	Min.	Max.	Unit
S18	I2S_RXD hold after I2S_BCLK	2	—	ns

Figure 30. I<sup>2</sup>S timing — slave modes

## 6.9 Human-machine interfaces (HMI)

### 6.9.1 TSI electrical specifications

Table 46. TSI electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V <sub>DDTSI</sub>	Operating voltage	1.71	—	3.6	V	
C <sub>ELE</sub>	Target electrode capacitance range	1	20	500	pF	1
f <sub>REFmax</sub>	Reference oscillator frequency	—	5.5	TBD	MHz	
f <sub>ELEmax</sub>	Electrode oscillator frequency	—	0.5	TBD	MHz	
C <sub>REF</sub>	Internal reference capacitor	TBD	1	TBD	pF	
V <sub>DELTA</sub>	Oscillator delta voltage	TBD	600	TBD	mV	
I <sub>REF</sub>	Reference oscillator current source base current	TBD	1	TBD	μA	2
I <sub>ELE</sub>	Electrode oscillator current source base current	TBD	1	TBD	μA	2
Pres5	Electrode capacitance measurement precision	—	TBD	TBD	%	3
Pres20	Electrode capacitance measurement precision	—	TBD	TBD	%	4
Pres100	Electrode capacitance measurement precision	—	TBD	TBD	%	5

Table continues on the next page...



**Table 46. TSI electrical specifications (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
MaxSens2 0	Maximum sensitivity @ 20 pF electrode	0.003	0.25	—	fF/count	6
MaxSens	Maximum sensitivity	0.003	—	—	fF/count	7
Res	Resolution	—	—	16	bits	
T <sub>Con20</sub>	Response time @ 20 pF	8	15	25	μs	8
I <sub>TSI_RUN</sub>	Current added in run mode	—	TBD	—	μA	
I <sub>TSI_LP</sub>	Low power mode current adder	—	1	TBD	μA	

1. The TSI module is functional with capacitance values outside this range. However, optimal performance is not guaranteed.
2. The programmable current source value is generated by multiplying the SCANC[REFCHRG] value and the base current.
3. Measured with a 5 pF electrode, reference oscillator frequency of 10 MHz, PS = 128, NSCN = 8; lext = 16.
4. Measured with a 20 pF electrode, reference oscillator frequency of 10 MHz, PS = 128, NSCN = 2; lext = 16.
5. Measured with a 20 pF electrode, reference oscillator frequency of 10 MHz, PS = 16, NSCN = 3; lext = 16.
6. Measured with a 20 pF electrode, reference oscillator frequency of ~5 MHz (I<sub>REF</sub> = 5 μA, REFCHRG = 4), PS = 128, NSCN = 2; lext = 16 (EXTCHRG = 15).
7. Typical value depends on the configuration used.
8. Time to do one complete measurement of the electrode. Sensitivity resolution of 0.0133 pF, PS = 0, NSCN = 0, 1 electrode, DELVOL = 2, EXTCHRG = 15.

## 7 Dimensions

### 7.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to <http://www.freescale.com> and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
80-pin LQFP	98ASS23174W
81-pin MAPBGA	98ASA10631D
144-pin LQFP	98ASS23177W
144-pin MAPBGA	98ASA00222D

## 8 Pinout

## 8.1 K60 Signal Multiplexing and Pin Assignments

The following table shows the signals available on each pin and the locations of these pins on the devices supported by this document. The Port Control Module is responsible for selecting which ALT functionality is available on each pin.

### NOTE

The 81-pin ballmap assignments are currently being developed. The • in the entries in this package column indicate which signals are present on the package.

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
—	L5	NC	NC	NC								
—	M5	NC	NC	NC								
—	A10	NC	NC	NC								
—	B10	NC	NC	NC								
—	C10	NC	NC	NC								
1	D3	PTE0	ADC1_SE4a	ADC1_SE4a	PTE0	SPI1_PCS1	UART1_TX	SDHC0_D1		I2C1_SDA		
2	D2	PTE1	ADC1_SE5a	ADC1_SE5a	PTE1	SPI1_SOUT	UART1_RX	SDHC0_D0		I2C1_SCL		
3	D1	PTE2	ADC1_SE6a	ADC1_SE6a	PTE2	SPI1_SCK	UART1_CTS_b	SDHC0_DCLK				
4	E4	PTE3	ADC1_SE7a	ADC1_SE7a	PTE3	SPI1_SIN	UART1_RTS_b	SDHC0_CMD				
5	E5	VDD	VDD	VDD								
6	F6	VSS	VSS	VSS								
7	E3	PTE4	DISABLED		PTE4	SPI1_PCS0	UART3_TX	SDHC0_D3				
8	E2	PTE5	DISABLED		PTE5	SPI1_PCS2	UART3_RX	SDHC0_D2				
9	E1	PTE6	DISABLED		PTE6	SPI1_PCS3	UART3_CTS_b	I2S0_MCLK		I2S0_CLKIN		
10	F4	PTE7	DISABLED		PTE7		UART3_RTS_b	I2S0_RXD				
11	F3	PTE8	DISABLED		PTE8			I2S0_RX_FS				
12	F2	PTE9	DISABLED		PTE9			I2S0_RX_BCLK				
13	F1	PTE10	DISABLED		PTE10			I2S0_TXD				
14	G4	PTE11	DISABLED		PTE11			I2S0_TX_FS				
15	G3	PTE12	DISABLED		PTE12			I2S0_TX_BCLK				
16	E6	VDD	VDD	VDD								
17	F7	VSS	VSS	VSS								
18	H3	VSS	VSS	VSS								

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
19	H1	USB0_DP	USB0_DP	USB0_DP								
20	H2	USB0_DM	USB0_DM	USB0_DM								
21	G1	VOUT33	VOUT33	VOUT33								
22	G2	VREGIN	VREGIN	VREGIN								
23	J1	ADC0_DP1	ADC0_DP1	ADC0_DP1								
24	J2	ADC0_DM1	ADC0_DM1	ADC0_DM1								
25	K1	ADC1_DP1	ADC1_DP1	ADC1_DP1								
26	K2	ADC1_DM1	ADC1_DM1	ADC1_DM1								
27	L1	PGA0_DP/ ADC0_DP0/ ADC1_DP3	PGA0_DP/ ADC0_DP0/ ADC1_DP3	PGA0_DP/ ADC0_DP0/ ADC1_DP3								
28	L2	PGA0_DM/ ADC0_DM0/ ADC1_DM3	PGA0_DM/ ADC0_DM0/ ADC1_DM3	PGA0_DM/ ADC0_DM0/ ADC1_DM3								
29	M1	PGA1_DP/ ADC1_DP0/ ADC0_DP3	PGA1_DP/ ADC1_DP0/ ADC0_DP3	PGA1_DP/ ADC1_DP0/ ADC0_DP3								
30	M2	PGA1_DM/ ADC1_DM0/ ADC0_DM3	PGA1_DM/ ADC1_DM0/ ADC0_DM3	PGA1_DM/ ADC1_DM0/ ADC0_DM3								
31	H5	VDDA	VDDA	VDDA								
32	G5	VREFH	VREFH	VREFH								
33	G6	VREFL	VREFL	VREFL								
34	H6	VSSA	VSSA	VSSA								
35	K3	ADC1_SE1 6/ CMP2_IN2/ ADC0_SE2 2	ADC1_SE1 6/ CMP2_IN2/ ADC0_SE2 2	ADC1_SE1 6/ CMP2_IN2/ ADC0_SE2 2								
36	J3	ADC0_SE1 6/ CMP1_IN2/ ADC0_SE2 1	ADC0_SE1 6/ CMP1_IN2/ ADC0_SE2 1	ADC0_SE1 6/ CMP1_IN2/ ADC0_SE2 1								
37	M3	VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE1 8	VREF_OUT	VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE1 8								
38	L3	DAC0_OUT/ CMP1_IN3/ ADC0_SE2 3	DAC0_OUT	DAC0_OUT/ CMP1_IN3/ ADC0_SE2 3								
39	L4	DAC1_OUT/ CMP2_IN3/ ADC1_SE2 3	DAC1_OUT	DAC1_OUT/ CMP2_IN3/ ADC1_SE2 3								
40	M7	XTAL32	XTAL32	XTAL32								

## Pinout

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
41	M6	EXTAL32	EXTAL32	EXTAL32								
42	L6	VBAT	VBAT	VBAT								
43	—	VDD	VDD	VDD								
44	—	VSS	VSS	VSS								
45	M4	PTE24	ADC0_SE17	ADC0_SE17	PTE24	CAN1_TX	UART4_TX			EWM_OUT_b		
46	K5	PTE25	ADC0_SE18	ADC0_SE18	PTE25	CAN1_RX	UART4_RX			EWM_IN		
47	K4	PTE26	DISABLED		PTE26		UART4_CTS_b	ENET_1588_CLKIN		RTC_CLKOUT	USB_CLKIN	
48	J4	PTE27	DISABLED		PTE27		UART4_RTS_b					
49	H4	PTE28	DISABLED		PTE28							
50	J5	PTA0	JTAG_TCLK/ SWD_CLK/ EZP_CLK	TSIO_CH1	PTA0	UART0_CTS_b	FTM0_CH5				JTAG_TCLK/ SWD_CLK	EZP_CLK
51	J6	PTA1	JTAG_TDI/ EZP_DI	TSIO_CH2	PTA1	UART0_RX	FTM0_CH6				JTAG_TDI	EZP_DI
52	K6	PTA2	JTAG_TDO/ TRACE_SWO/ EZP_DO	TSIO_CH3	PTA2	UART0_TX	FTM0_CH7				JTAG_TDO/ TRACE_SWO	EZP_DO
53	K7	PTA3	JTAG_TMS/ SWD_DIO	TSIO_CH4	PTA3	UART0_RTS_b	FTM0_CH0				JTAG_TMS/ SWD_DIO	
54	L7	PTA4	NMI_b/ EZP_CS_b	TSIO_CH5	PTA4		FTM0_CH1				NMI_b	EZP_CS_b
55	M8	PTA5	DISABLED		PTA5		FTM0_CH2	RMII0_RXER/ MII0_RXER	CMP2_OUT	I2S0_RX_BCLK	JTAG_TRST	
56	E7	VDD	VDD	VDD								
57	G7	VSS	VSS	VSS								
58	J7	PTA6	DISABLED		PTA6		FTM0_CH3				TRACE_CLKOUT	
59	J8	PTA7	ADC0_SE10	ADC0_SE10	PTA7		FTM0_CH4				TRACE_D3	
60	K8	PTA8	ADC0_SE11	ADC0_SE11	PTA8		FTM1_CH0			FTM1_QD_PHA	TRACE_D2	
61	L8	PTA9	DISABLED		PTA9		FTM1_CH1	MII0_RXD3		FTM1_QD_PHB	TRACE_D1	
62	M9	PTA10	DISABLED		PTA10		FTM2_CH0	MII0_RXD2		FTM2_QD_PHA	TRACE_D0	
63	L9	PTA11	DISABLED		PTA11		FTM2_CH1	MII0_RXCLK		FTM2_QD_PHB		
64	K9	PTA12	CMP2_IN0	CMP2_IN0	PTA12	CAN0_TX	FTM1_CH0	RMII0_RXD1/ MII0_RXD1		I2S0_TXD	FTM1_QD_PHA	

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
65	J9	PTA13	CMP2_IN1	CMP2_IN1	PTA13	CAN0_RX	FTM1_CH1	RMIIO_RXD0/ MII0_RXD0		I2S0_TX_FS	FTM1_QD_PHB	
66	L10	PTA14	DISABLED		PTA14	SPI0_PCS0	UART0_TX	RMIIO_CRS_DV/ MII0_RXDV		I2S0_TX_BCLK		
67	L11	PTA15	DISABLED		PTA15	SPI0_SCK	UART0_RX	RMIIO_TXEN/ MII0_TXEN		I2S0_RXD		
68	K10	PTA16	DISABLED		PTA16	SPI0_SOUT	UART0_CTS_b	RMIIO_TXD0/ MII0_TXD0		I2S0_RX_FS		
69	K11	PTA17	ADC1_SE17	ADC1_SE17	PTA17	SPI0_SIN	UART0_RTS_b	RMIIO_TXD1/ MII0_TXD1		I2S0_MCLK	I2S0_CLKIN	
70	E8	VDD	VDD	VDD								
71	G8	VSS	VSS	VSS								
72	M12	PTA18	EXTAL	EXTAL	PTA18		FTM0_FLT2	FTM_CLKIN0				
73	M11	PTA19	XTAL	XTAL	PTA19		FTM1_FLT0	FTM_CLKIN1		LPT0_ALT1		
74	L12	RESET_b	RESET_b	RESET_b								
75	K12	PTA24	DISABLED		PTA24			MII0_TXD2		FB_A29		
76	J12	PTA25	DISABLED		PTA25			MII0_TXCLK		FB_A28		
77	J11	PTA26	DISABLED		PTA26			MII0_TXD3		FB_A27		
78	J10	PTA27	DISABLED		PTA27			MII0_CRS		FB_A26		
79	H12	PTA28	DISABLED		PTA28			MII0_TXER		FB_A25		
80	H11	PTA29	DISABLED		PTA29			MII0_COL		FB_A24		
81	H10	PTB0	/ ADC0_SE8/ ADC1_SE8/ TSIO_CH0	/ ADC0_SE8/ ADC1_SE8/ TSIO_CH0	PTB0	I2C0_SCL	FTM1_CH0	RMIIO_MDI0/ MII0_MDIO		FTM1_QD_PHA		
82	H9	PTB1	/ ADC0_SE9/ ADC1_SE9/ TSIO_CH6	/ ADC0_SE9/ ADC1_SE9/ TSIO_CH6	PTB1	I2C0_SDA	FTM1_CH1	RMIIO_MDC/ MII0_MDC		FTM1_QD_PHB		
83	G12	PTB2	/ ADC0_SE12/ TSIO_CH7	/ ADC0_SE12/ TSIO_CH7	PTB2	I2C0_SCL	UART0_RTS_b	ENET0_1588_TMR0		FTM0_FLT3		
84	G11	PTB3	/ ADC0_SE13/ TSIO_CH8	/ ADC0_SE13/ TSIO_CH8	PTB3	I2C0_SDA	UART0_CTS_b	ENET0_1588_TMR1		FTM0_FLT0		
85	G10	PTB4	/ ADC1_SE10	/ ADC1_SE10	PTB4			ENET0_1588_TMR2		FTM1_FLT0		

## Pinout

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
86	G9	PTB5	/ ADC1_SE1 1	/ ADC1_SE1 1	PTB5			ENET0_158 8_TMR3		FTM2_FLT0		
87	F12	PTB6	/ ADC1_SE1 2	/ ADC1_SE1 2	PTB6				FB_AD23			
88	F11	PTB7	/ ADC1_SE1 3	/ ADC1_SE1 3	PTB7				FB_AD22			
89	F10	PTB8			PTB8		UART3_RT S_b		FB_AD21			
90	F9	PTB9			PTB9	SPI1_PCS1	UART3_CT S_b		FB_AD20			
91	E12	PTB10	/ ADC1_SE1 4	/ ADC1_SE1 4	PTB10	SPI1_PCS0	UART3_RX		FB_AD19	FTM0_FLT1		
92	E11	PTB11	/ ADC1_SE1 5	/ ADC1_SE1 5	PTB11	SPI1_SCK	UART3_TX		FB_AD18	FTM0_FLT2		
93	H7	VSS	VSS	VSS								
94	F5	VDD	VDD	VDD								
95	E10	PTB16	/TSIO_CH9	/TSIO_CH9	PTB16	SPI1_SOUT	UART0_RX		FB_AD17	EWM_IN		
96	E9	PTB17	/TSIO_CH10	/TSIO_CH10	PTB17	SPI1_SIN	UART0_TX		FB_AD16	EWM_OUT _b		
97	D12	PTB18	/TSIO_CH11	/TSIO_CH11	PTB18	CAN0_TX	FTM2_CH0	I2S0_TX_B CLK	FB_AD15	FTM2_QD_ PHA		
98	D11	PTB19	/TSIO_CH12	/TSIO_CH12	PTB19	CAN0_RX	FTM2_CH1	I2S0_TX_F S	FB_OE_b	FTM2_QD_ PHB		
99	D10	PTB20			PTB20	SPI2_PCS0			FB_AD31	CMP0_OUT		
100	D9	PTB21			PTB21	SPI2_SCK			FB_AD30	CMP1_OUT		
101	C12	PTB22			PTB22	SPI2_SOUT			FB_AD29	CMP2_OUT		
102	C11	PTB23			PTB23	SPI2_SIN	SPI0_PCS5		FB_AD28			
103	B12	PTC0	/ ADC0_SE1 4/ TSIO_CH13	/ ADC0_SE1 4/ TSIO_CH13	PTC0	SPI0_PCS4	PDB0_EXT RG	I2S0_TXD	FB_AD14			
104	B11	PTC1	/ ADC0_SE1 5/ TSIO_CH14	/ ADC0_SE1 5/ TSIO_CH14	PTC1	SPI0_PCS3	UART1_RT S_b	FTM0_CH0	FB_AD13			
105	A12	PTC2	/ ADC0_SE4 b/ CMP1_IN0/ TSIO_CH15	/ ADC0_SE4 b/ CMP1_IN0/ TSIO_CH15	PTC2	SPI0_PCS2	UART1_CT S_b	FTM0_CH1	FB_AD12			
106	A11	PTC3	/CMP1_IN1	/CMP1_IN1	PTC3	SPI0_PCS1	UART1_RX	FTM0_CH2	FB_CLKOU T			
107	H8	VSS	VSS	VSS								

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
108	—	VDD	VDD	VDD								
109	A9	PTC4			PTC4	SPI0_PCS0	UART1_TX	FTM0_CH3	FB_AD11	CMP1_OUT		
110	D8	PTC5			PTC5	SPI0_SCK		LPT0_ALT2	FB_AD10	CMP0_OUT		
111	C8	PTC6	/CMP0_IN0	/CMP0_IN0	PTC6	SPI0_SOUT	PDB0_EXTRG		FB_AD9			
112	B8	PTC7	/CMP0_IN1	/CMP0_IN1	PTC7	SPI0_SIN			FB_AD8			
113	A8	PTC8	/ADC1_SE4b/ CMP0_IN2	/ADC1_SE4b/ CMP0_IN2	PTC8		I2S0_MCLK	I2S0_CLKIN	FB_AD7			
114	D7	PTC9	/ADC1_SE5b/ CMP0_IN3	/ADC1_SE5b/ CMP0_IN3	PTC9			I2S0_RX_BCLK	FB_AD6	FTM2_FLT0		
115	C7	PTC10	/ADC1_SE6b/ CMP0_IN4	/ADC1_SE6b/ CMP0_IN4	PTC10	I2C1_SCL		I2S0_RX_FS	FB_AD5			
116	B7	PTC11	/ADC1_SE7b	/ADC1_SE7b	PTC11	I2C1_SDA		I2S0_RXD	FB_RW_b			
117	A7	PTC12			PTC12		UART4_RTS_b		FB_AD27			
118	D6	PTC13			PTC13		UART4_CTS_b		FB_AD26			
119	C6	PTC14			PTC14		UART4_RX		FB_AD25			
120	B6	PTC15			PTC15		UART4_TX		FB_AD24			
121	—	VSS	VSS	VSS								
122	—	VDD	VDD	VDD								
123	A6	PTC16			PTC16	CAN1_RX	UART3_RX	ENET0_1588_TMR0	FB_CS5_b/ FB_TSIZ1/ FB_BE23_16_BLS15_8_b			
124	D5	PTC17			PTC17	CAN1_TX	UART3_TX	ENET0_1588_TMR1	FB_CS4_b/ FB_TSIZ0/ FB_BE31_24_BLS7_0_b			
125	C5	PTC18			PTC18		UART3_RTS_b	ENET0_1588_TMR2	FB_TBST_b/ FB_CS2_b/ FB_BE15_8_BLS23_16_b			
126	B5	PTC19			PTC19		UART3_CTS_b	ENET0_1588_TMR3	FB_CS3_b/ FB_BE7_0_BLS31_24_b	FB_TA_b		

## Pinout

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
127	A5	PTD0			PTD0	SPI0_PCS0	UART2_RTS_b		FB_ALE/ FB_CS1_b/ FB_TS_b			
128	D4	PTD1	/ ADC0_SE5_b	/ ADC0_SE5_b	PTD1	SPI0_SCK	UART2_CTS_b		FB_CS0_b			
129	C4	PTD2			PTD2	SPI0_SOUT	UART2_RX		FB_AD4			
130	B4	PTD3			PTD3	SPI0_SIN	UART2_TX		FB_AD3			
131	A4	PTD4			PTD4	SPI0_PCS1	UART0_RTS_b	FTM0_CH4	FB_AD2	EWM_IN		
132	A3	PTD5	/ ADC0_SE6_b	/ ADC0_SE6_b	PTD5	SPI0_PCS2	UART0_CTS_b	FTM0_CH5	FB_AD1	EWM_OUT_b		
133	A2	PTD6	/ ADC0_SE7_b	/ ADC0_SE7_b	PTD6	SPI0_PCS3	UART0_RX	FTM0_CH6	FB_AD0	FTM0_FLT0		
134	M10	VSS	VSS	VSS								
135	F8	VDD	VDD	VDD								
136	A1	PTD7			PTD7	CMT_IRO	UART0_TX	FTM0_CH7		FTM0_FLT1		
137	C9	PTD8	DISABLED		PTD8	I2C0_SCL				FB_A16		
138	B9	PTD9	DISABLED		PTD9	I2C0_SDA				FB_A17		
139	B3	PTD10	DISABLED		PTD10					FB_A18		
140	B2	PTD11	DISABLED		PTD11	SPI2_PCS0		SDHC0_CLKIN		FB_A19		
141	B1	PTD12	DISABLED		PTD12	SPI2_SCK		SDHC0_D4		FB_A20		
142	C3	PTD13	DISABLED		PTD13	SPI2_SOUT		SDHC0_D5		FB_A21		
143	C2	PTD14	DISABLED		PTD14	SPI2_SIN		SDHC0_D6		FB_A22		
144	C1	PTD15	DISABLED		PTD15	SPI2_PCS1		SDHC0_D7		FB_A23		

## 8.2 K60 Pinouts

The below figure shows the pinout diagram for the devices supported by this document. Many signals may be multiplexed onto a single pin. To determine what signals can be used on which pin, see the previous section.



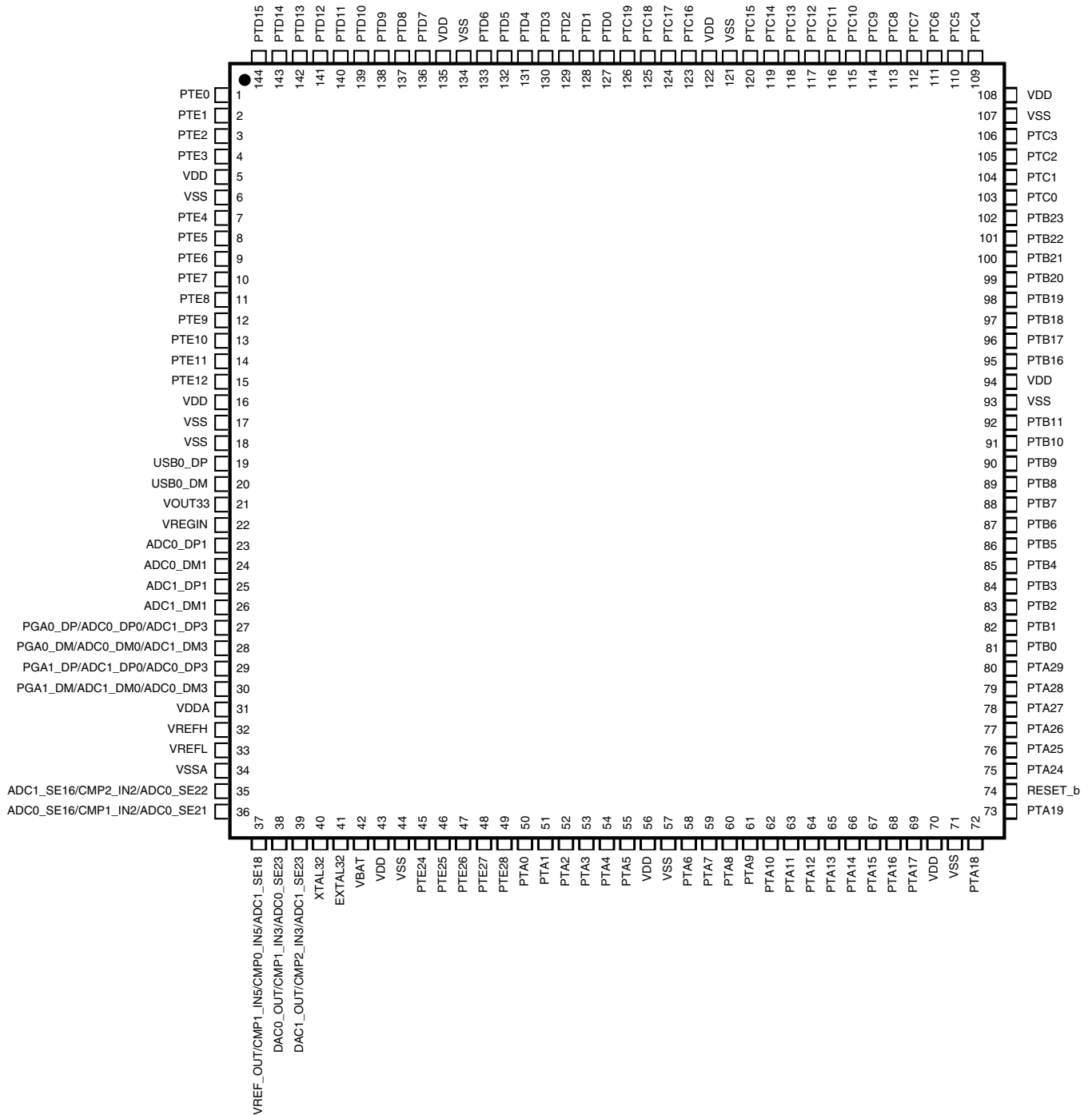


Figure 31. K60 144 LQFP Pinout Diagram

## Revision History

	1	2	3	4	5	6	7	8	9	10	11	12	
A	PTD7	PTD6	PTD5	PTD4	PTD0	PTC16	PTC12	PTC8	PTC4	NC	PTC3	PTC2	A
B	PTD12	PTD11	PTD10	PTD3	PTC19	PTC15	PTC11	PTC7	PTD9	NC	PTC1	PTC0	B
C	PTD15	PTD14	PTD13	PTD2	PTC18	PTC14	PTC10	PTC6	PTD8	NC	PTB23	PTB22	C
D	PTE2	PTE1	PTE0	PTD1	PTC17	PTC13	PTC9	PTC5	PTB21	PTB20	PTB19	PTB18	D
E	PTE6	PTE5	PTE4	PTE3	VDD	VDD	VDD	VDD	PTB17	PTB16	PTB11	PTB10	E
F	PTE10	PTE9	PTE8	PTE7	VDD	VSS	VSS	VDD	PTB9	PTB8	PTB7	PTB6	F
G	VOUT33	VREGIN	PTE12	PTE11	VREFH	VREFL	VSS	VSS	PTB5	PTB4	PTB3	PTB2	G
H	USB0_DP	USB0_DM	VSS	PTE28	VDDA	VSSA	VSS	VSS	PTB1	PTB0	PTA29	PTA28	H
J	ADC0_DP1	ADC0_DM1	ADC0_SE16/ CMP1_IN2/ ADC0_SE21	PTE27	PTA0	PTA1	PTA6	PTA7	PTA13	PTA27	PTA26	PTA25	J
K	ADC1_DP1	ADC1_DM1	ADC1_SE16/ CMP2_IN2/ ADC0_SE22	PTE26	PTE25	PTA2	PTA3	PTA8	PTA12	PTA16	PTA17	PTA24	K
L	PGA0_DP/ ADC0_DP0/ ADC1_DP3	PGA0_DM/ ADC0_DM0/ ADC1_DM3	DAC0_OUT/ CMP1_IN3/ ADC0_SE23	DAC1_OUT/ CMP2_IN3/ ADC1_SE23	NC	VBAT	PTA4	PTA9	PTA11	PTA14	PTA15	RESET_b	L
M	PGA1_DP/ ADC1_DP0/ ADC0_DP3	PGA1_DM/ ADC1_DM0/ ADC0_DM3	VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18	PTE24	NC	EXTAL32	XTAL32	PTA5	PTA10	VSS	PTA19	PTA18	M

**Figure 32. K60 144 MAPBGA Pinout Diagram**

## 9 Revision History

The following table provides a revision history for this document.

**Table 47. Revision History**

Rev. No.	Date	Substantial Changes
1	11/2010	Initial public revision

*Table continues on the next page...*

**Table 47. Revision History (continued)**

Rev. No.	Date	Substantial Changes
2	3/2011	Many updates throughout Corrected 81- and 104-pin package codes
3	3/2011	Added sections that were inadvertently removed in previous revision
4	3/2011	Reworded $I_{IC}$ footnote in "Voltage and Current Operating Requirements" table. Added paragraph to "Peripheral operating requirements and behaviors" section. Added "JTAG full voltage range electricals" table to the "JTAG electricals" section.

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